

Doc. Number:

- ☒ Tentative Specification
- ☐ Preliminary Specification
- ☐ Approval Specification

MODEL NO.: P080LDE
SUFFIX: DF1

Customer:

APPROVED BY

SIGNATURE

Name / Title _____

Note : _____

 Please return 1 copy for your confirmation with your signature and comments.

| Approved By | Checked By | Prepared By |
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| Version | Date | Page | Description |
|---------|--------------|--------|--------------------|
| V 1 | 04, 16, 2014 | All | First Release |
| V 1.1 | 07, 25, 2014 | 34, 35 | RA Spec |
| V1.2 | 09, 01, 2014 | 5~44 | Update Chapter 1~8 |
| | | | |
| | | | |
| | | | |
| | | | |
| | | | |

1. General Description of TDM

1.1 Overview

P080LDE-DF1 is a 8" (8" diagonal) TDM (Touch Display Module) with **10 pins I2C** interface for Touch Module and TFT Liquid Crystal Display module with LED Backlight unit and **45 pins MIPI** interface. This module supports 1200 x 1920 WUXGA mode.

1.2 General Specifications of TDM

| Item | Specification | Unit | Note |
|---------------------------------|---|-------|--------------------|
| Screen Size | 8" diagonal | | |
| Driver Element | a-si TFT active matrix | - | |
| Pixel Number | 1200 x R.G.B. x 1920 | pixel | |
| Pixel Pitch | 0.0897 (H) x 0.0897 (V) | mm | |
| Pixel Arrangement | RGB vertical stripe | - | |
| Display Colors | 16,777,216 (8bit color depth) | color | |
| Transmissive Mode | Normally black | - | |
| Luminance, White | LCM: 400 | Cd/m2 | |
| | TDM: 380 | | |
| Power Consumption | LCM: Total 2.3 W (Max.) (panel 0.55 W (Max.), BL 1.75W (Max.)) | | 10 fingers touches |
| | TDM : 2.4 W (Max.) | | |
| Touch Technology | Projected Capacitive Multi-Touch Panel | | |
| Number of Channels | 25(X)-39(Y) | | |
| TPM/LCM Bonding Type | Direct-bond | | UV-OCA: 0.2mm |
| Numbers of Touch | 10 Points | | |
| TP Reporting rate | <60 Hz (16.7 ms) | | |
| Minimum stylus diameter | 5 mm | | |
| Sensor Glass | Soda lime 0.7mm | | |
| TP unit cell pattern pitch size | 4.3456x 4.4415 | mm | |
| TP Type | WIS | | |
| Touch Module Outline | 119.44 x 211.8 (mm) | mm | |
| Touch Active Area | 108.64 x 173.224 (mm) | mm | |
| Touch Windows Visible Area | 108.64 x 173.224 (mm) | mm | |
| TP Module Thickness (Max) | TPM:0.7 (w/o FPCA) 1.8 (W/i FPCa) | mm | UV-OCA: 0.2mm |
| | TPM:0.7 | | |
| Module Weight (Max) | LCM:82.2 | g | |
| | TPM:46 | | |
| | TDM:128.2 | | |
| AR/AG/ASF | No | | |

Note (1) The specified power consumption (with converter efficiency) is under the conditions at **VDD= 3.3V, fv = 60 Hz, Brightness (5 point average) = 400nits, IF_LED = 22mA** and Ta = 25 ± 2 °C, whereas **white** pattern is displayed.

1.3 General TP Sensor Specifications

| Item | Specification | Unit | Note |
|--------------------|------------------------------------|---------|------|
| Bridge-Type | Metal | | |
| Process Flow | BM/ITO/DE/ME/PAS | | |
| BM Thickness | 1.4 | um | |
| BM OD | >4 | | |
| ITO Resistance | <50 | ohm/sq. | |
| DE Thickness | 1.6 | um | |
| ME Resistance | ≤ 0.35 | ohm/sq | |
| PAS Thickness | 2.3 | um | |
| Index Match Film | Yes | | |
| Transmittance, T% | Among visible light spectrum > 87% | | |
| Transmittance, a* | -1.5 < a* < 1.5 | | |
| Transmittance, b* | -2 < b* < 4.5 | | |
| Reflection, R% | NA | | |
| Reflection, a* | NA | | |
| Reflection, b* | NA | | |
| Haze | < 1% | % | |
| Number of Channels | 25(X)-39(Y) | | |
| Trace line/space | 20/25 | | |

1.4 WIS Specifications

| Item | Specification | Unit | Note |
|---------------------------------|--|------|------|
| Cover Lens Thickness | 0.7±0.05 | mm | |
| Cover Type | Glass (WIS) | | |
| Cover Lens Substrate | Soda-lime | | |
| ASF | Without | | |
| Light Sensor ink | IR Ink Transmittance : 10%-20% at 540nm & > 70% at 850nm (Black color) | | |
| Logo | No | | |
| Logo method | NA | | |
| Logo Color | NA | | |
| Drill Hole | No | | |
| Function Hole | Camera/IR Hole | | |
| Hole Optical Spec. | NA | | |
| 4PB(B10) (Mpa) | 160 | | |
| Surface Treatment | No | | |
| Pencil hardness | >7H | | |
| Light Sensor Hole Transmittance | 10%-20% at 540nm & > 70% at 850nm | | |
| Corner spec | 四角雲形線 | | |
| 2nd strength | No | | |
| Outline Dimension (mm) | 119.44 x 211.8 | mm | |
| Visible Area (mm) | 108.64 x 173.224 | mm | |
| Weight(g) | Glass :44.3g FPC:0.6g OCA:7.4g | | |

2. Optical Characteristics

2.1 Test Conditions of LCM

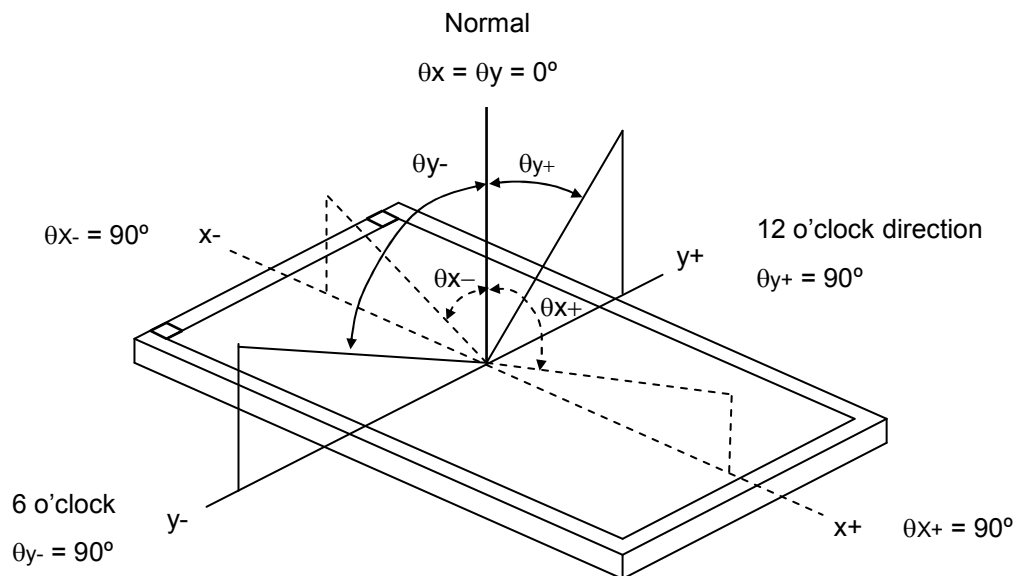
| Item | Symbol | Value | Unit |
|-----------------------------|---|-------|------|
| Ambient Temperature | Ta | 25±2 | °C |
| Ambient Humidity | Ha | 50±10 | %RH |
| Supply Voltage | VDDI | 1.8 | V |
| | VCI | 3.3 | V |
| Input Signal | According to typical value in "3. ELECTRICAL CHARACTERISTICS" | | |
| LED Light Bar Input Current | I _L | 66 | mA |

The measurement methods of optical characteristics are shown in Section 5.2. The following items should be measured under the test conditions described in Section 5.1 and stable environment shown in Note (5)

2.2 Optical Specifications of TDM

| Item | | Symbol | Condition | Min. | Typ. | Max. | Unit | Note |
|------------------------------|------------|--------------------------------|--------------------------------------|---------------|---------|---------------|-----------------------|------------------|
| Contrast Ratio | | CR | $\theta_x=0^\circ, \theta_Y=0^\circ$ | 600 | 800 | - | - | (2),(5) , (7) |
| Response Time | | T _R +T _F | | - | 25 | 30 | ms | (3) ,(7) |
| CP Luminance of White | LCM | L _{CP} | | 340 | 400 | - | Cd/ m ² | (4), (6), (7) |
| | TDM | | | 320 | 380 | | | |
| Color Chromaticity | White | W _x | R=G=B=255 Gray scale | Typ – 0.03 | (0.313) | Typ + 0.03 | - - | (4), (6), (7) |
| | | W _y | | | (0.329) | | | |
| | Red | R _x | | | 0.613 | | | |
| | | R _y | | | 0.350 | | | |
| | Green | G _x | | | 0.325 | | | |
| | | G _y | | | 0.605 | | | |
| | Blue | B _x | | | 0.152 | | | |
| | | B _y | | | 0.071 | | | |
| NTSC | | | $\theta_x=0^\circ, \theta_Y=0^\circ$ | 55 | 60 | - | % | (5), (6), (7) |
| Viewing Angle | Horizontal | x- + x+ | CR > 10 | 170 | 178 | - | deg. | (1), (5), (7) |
| | Vertical | y- + y+ | | 170 | 178 | - | | |
| White Variation of 9 Points | | δW_{9p} | $\theta_x=0^\circ, \theta_Y=0^\circ$ | 80 | | - | % | (5), (6), (7) |
| White Variation of 13 Points | | δW_{13p} | $\theta_x=0^\circ, \theta_Y=0^\circ$ | 67 | | - | % | (5), (6), (7) |

Note (1) Definition of Viewing Angle (θ_x , θ_y):



Note (2) Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression.

$$\text{Contrast Ratio (CR)} = L_{255} / L_0$$

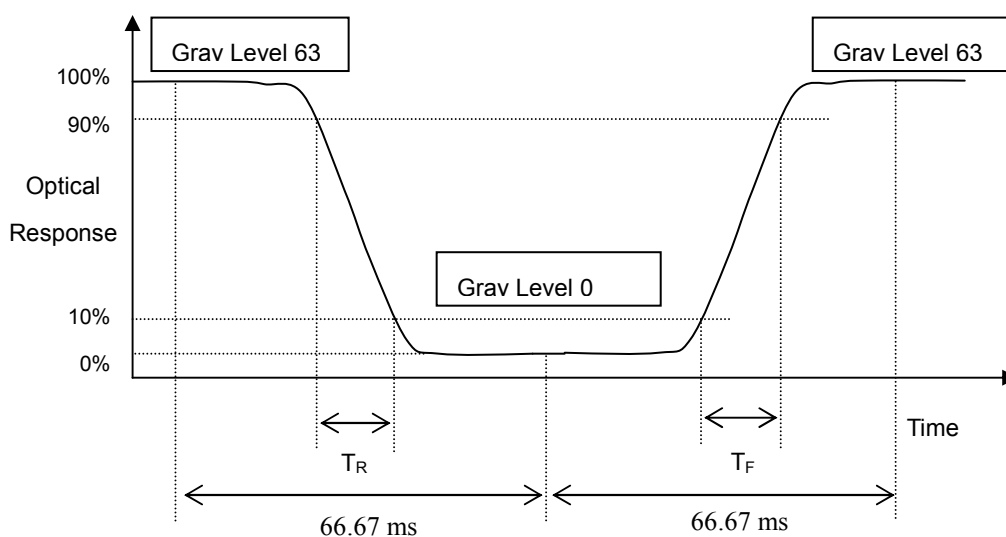
L255: Luminance of gray level 255

L 0: Luminance of gray level 0

$$CR = CR(1)$$

CR (X) is corresponding to the Contrast Ratio of the point X at Figure in Note (6).

Note (3) Definition of Response Time (T_R , T_F):



Note (4) Definition of Center Point Luminance of White (L_{CP}):

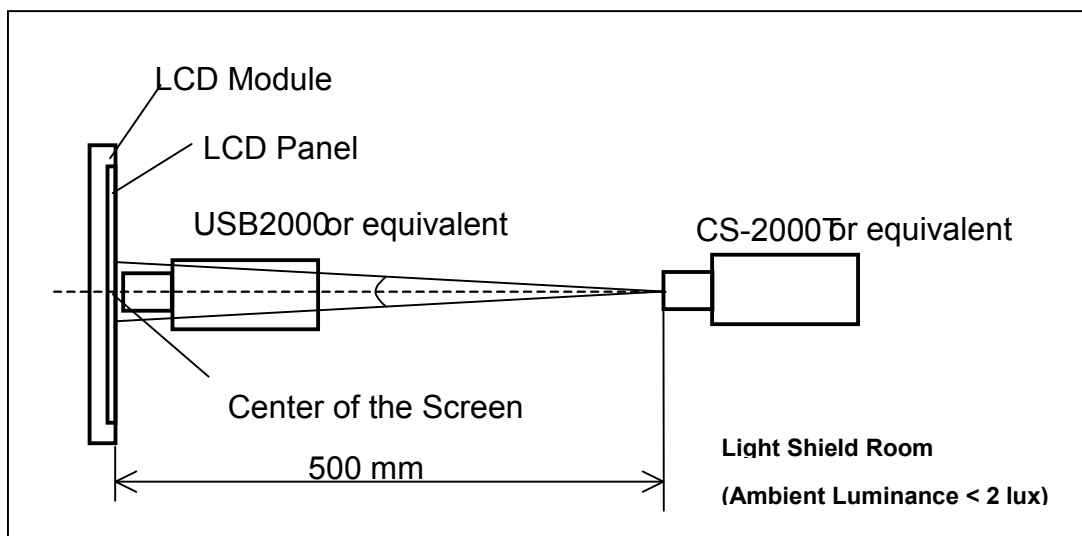
Measure the luminance of gray level 63 at center point

$$L_{CP} = L(5)$$

$L(x)$ is corresponding to the luminance of the point X at Figure in Note (6)

Note (5) Measurement Setup:

The LCD module should be stabilized at given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 20 minutes in a windless room.

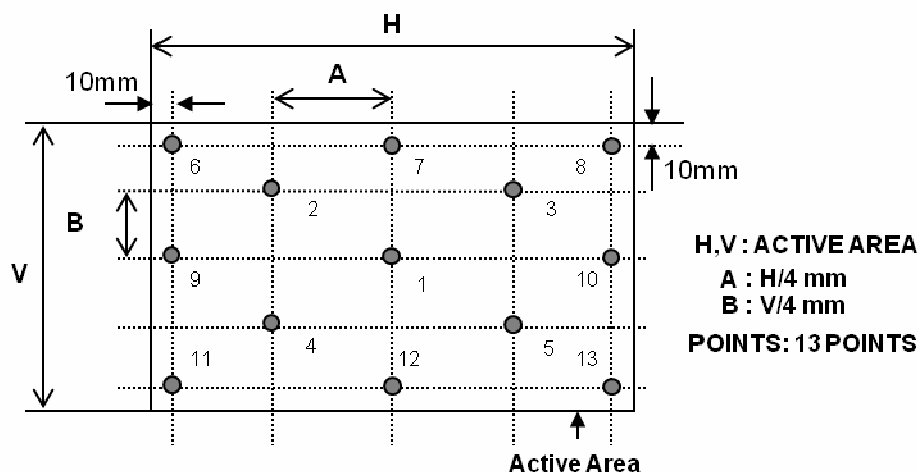


Note (6) Definition of White Variation (δW):

Measure the luminance of gray level 63 at 13 points

$$\delta W_{9p} = \{ \text{Minimum } [L(1) \sim L(13)] / \text{Maximum } [L(1) \sim L(13)] \} * 100\%$$

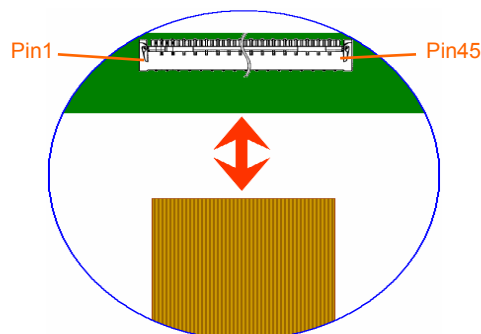
Active area



Note (7) The listed optical specifications refer to the initial value of manufacture, but the condition of the specifications after long-term operation will not be warranted.

3. Electrical Specifications of LCM

3.1 CONNECTOR TYPE



Please refer Appendix Outline Drawing for detail design.

Connector Part No.: **I-PEX 20584-045E-01**

3.2 ABSOLUTE MAXIMUM RATINGS

3.2.1 ABSOLUTE RATINGS OF ENVIRONMENT

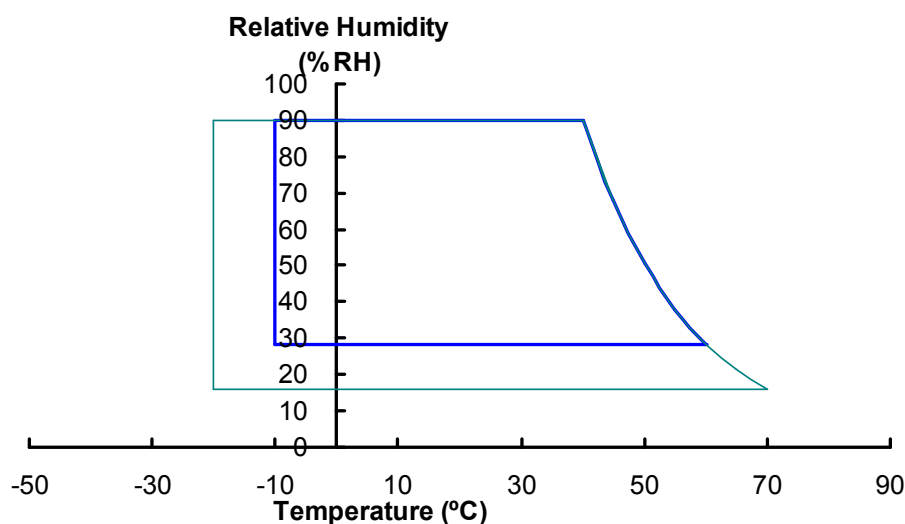
| Item | Symbol | Value | | Unit | Note |
|-------------------------------|----------|-------|------|------|----------|
| | | Min. | Max. | | |
| Storage Temperature | T_{ST} | -20 | +70 | °C | (1) |
| Operating Ambient Temperature | T_{OP} | -10 | +60 | °C | (1), (2) |

Note (1) (a) 90 %RH Max. ($T_a \leq 40$ °C).

(b) Wet-bulb temperature should be 39 °C Max. ($T_a > 40$ °C).

(c) No condensation.

Note (2) The temperature of panel surface should be -10 °C min. and 70 °C max.



3.3 ELECTRICAL ABSOLUTE RATINGS

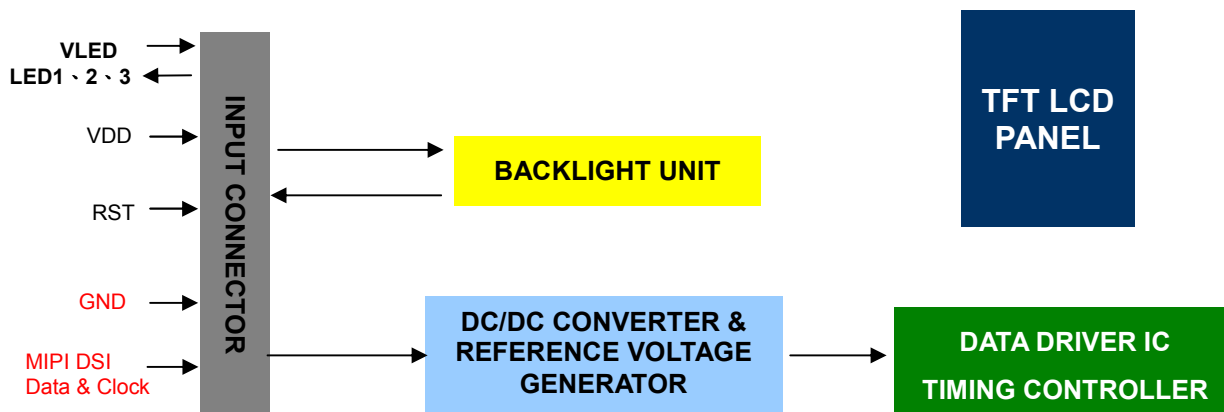
3.3.1 TFT LCD MODULE

| Item | Symbol | Value | | Unit | Note |
|-----------------------------|------------|-------------|-------------|----------|------|
| | | Min. | Max. | | |
| Power Supply Voltage | VDD | +2.7 | +3.6 | V | (1) |

Note (1) Stresses beyond those listed in above “ELECTRICAL ABSOLUTE RATINGS” may cause permanent damage to the device. Normal operation should be restricted to the conditions described in “ELECTRICAL CHARACTERISTICS”.

3.4. ELECTRICAL SPECIFICATIONS

3.4.1 FUNCTION BLOCK DIAGRAM



3.4.2. INTERFACE CONNECTIONS

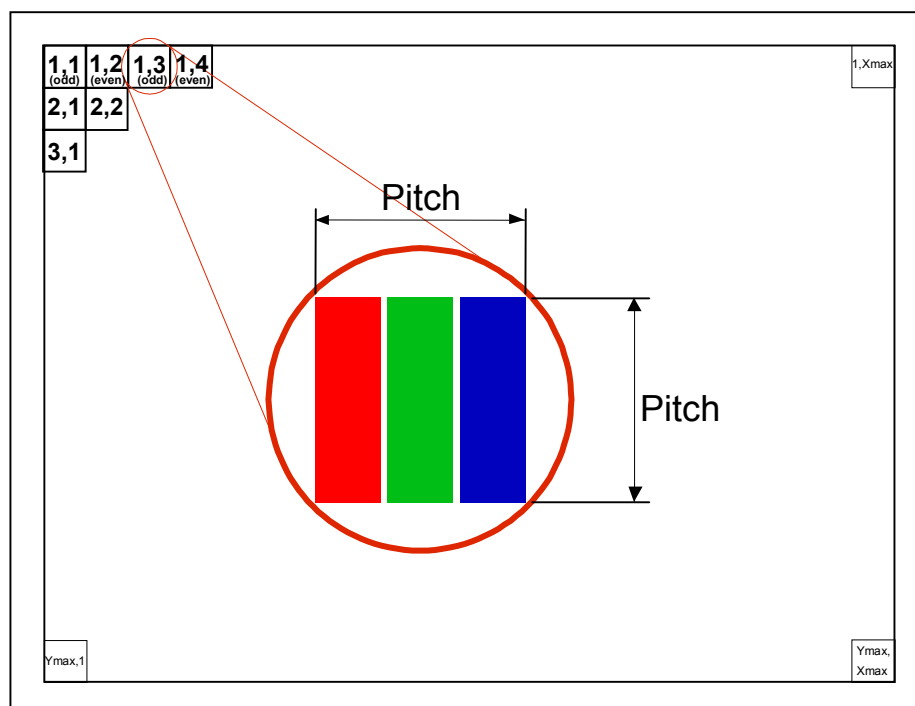
PIN ASSIGNMENT

| Pin | Symbol | I/O | Description | Remark |
|-----|----------|-----|--|-----------|
| 1 | NC(WPN) | | No connection, please keep it floating | |
| 2 | GND | P | Ground | |
| 3 | ID1 | | Ground | |
| 4 | ID2 | | No connection | |
| 5 | NC(SDA) | | No connection, please keep it floating | |
| 6 | NC(SCL) | | No connection, please keep it floating | |
| 7 | NC(MTP) | | No connection, please keep it floating | 7.4V~7.6V |
| 8 | GND | P | Ground | |
| 9 | ID3 | | Ground | |
| 10 | NC(BIST) | | No connection, please keep it floating | 1.4V~1.6V |
| 11 | GND | P | Ground | |
| 12 | NC | | No connection | |
| 13 | NC | | No connection | |
| 14 | VDD | P | 3.3V input | 3.0V~3.6V |
| 15 | VDD | P | 3.3V input | 3.0V~3.6V |
| 16 | VDD | P | 3.3V input | 3.0V~3.6V |
| 17 | VDD | P | 3.3V input | 3.0V~3.6V |
| 18 | GND | P | Ground | |
| 19 | NC | | No connection | |
| 20 | RESET | I | Device reset signal | 3.0V~3.6V |
| 21 | GND | P | Ground | |
| 22 | D0_P | I | MIPI data 0 positive signal | |
| 23 | D0_N | I | MIPI data 0 negative signal | |
| 24 | GND | P | Ground | |

| | | | | |
|----|-------|---|-----------------------------|-------|
| 25 | D1_P | I | MIPI data 1 positive signal | |
| 26 | D1_N | I | MIPI data 1 negative signal | |
| 27 | GND | P | Ground | |
| 28 | CLK_P | I | MIPI CLK positive signal | |
| 29 | CLK_N | I | MIPI CLK negative signal | |
| 30 | GND | P | Ground | |
| 31 | D2_P | I | MIPI data 2 positive signal | |
| 32 | D2_N | I | MIPI data 2 negative signal | |
| 33 | GND | P | Ground | |
| 34 | D3_P | I | MIPI data 3 positive signal | |
| 35 | D3_N | I | MIPI data 3 negative signal | |
| 36 | GND | P | Ground | |
| 37 | LED3 | P | LED Cathode | |
| 38 | LED2 | P | LED Cathode | |
| 39 | LED1 | P | LED Cathode | |
| 40 | GND | P | Ground | |
| 41 | VLED | P | LED Anode | 22.4V |
| 42 | VLED | P | LED Anode | 22.4V |
| 43 | VLED | P | LED Anode | 22.4V |
| 44 | GND | P | Ground | |
| 45 | NC | | No connection | |

Note (1) The first pixel is odd as shown in the following figure.

Note (2) Normal operation/BIST pattern selection. (Control by MIPI LP Command)



3.5 Electrical Characteristics

3.5.1 LCD Electronics Specifications

| Item | Symbol | Values | | | Unit | Remark |
|------------------------------|------------------|------------------|------|---------|------|-----------------|
| | | Min. | Typ. | Max. | | |
| Power supply voltage | VDD | 3.0 | 3.3 | 3.6 | V | |
| VDD High level input voltage | V _{IH1} | 0.7 VDD | - | VDDI | V | For I/O circuit |
| VDD Low level input voltage | V _{IL1} | 0 | - | 0.3 VDD | V | |
| Power Supply Current | White | I _{VDD} | 116 | 120 | mA | Note (2) |

Note (1) The ambient temperature is $T_a = 25 \pm 2^\circ\text{C}$.

Note (2) The specified power supply current is under the conditions at $V_{DD} = 3.3\text{ V}$, $T_a = 25 \pm 2^\circ\text{C}$, DC Current and $f_v = 60\text{ Hz}$, whereas a power dissipation check pattern below is displayed.

b. White Pattern



Active Area

3.6 LED Converter Specifications

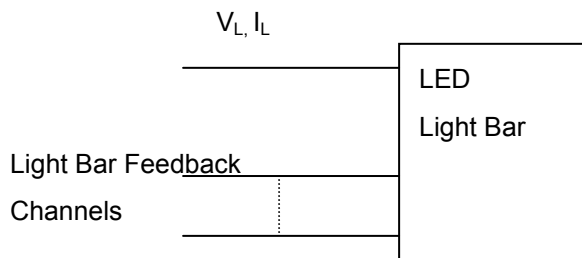
N/A

3.7 Backlight Unit

$T_a = 25 \pm 2^\circ\text{C}$

| Parameter | Symbol | Value | | | Unit | Note |
|------------------------------------|-----------------|--------|------|------|------|------------------|
| | | Min. | Typ. | Max. | | |
| LED Light Bar Power Supply Voltage | V _L | | | 23 | V | (1)(2)(Duty100%) |
| LED Light Bar Power Supply Current | I _L | - | 66 | - | mA | |
| Power Consumption | P _L | - | | 1.5 | W | (3) |
| LED Life Time | L _{BL} | 15,000 | - | - | Hrs | (4) |

Note (1) LED current is measured by utilizing a high frequency current meter as shown below :



Note (2) For better LED light bar driving quality, it is recommended to utilize the adaptive boost converter with current balancing function to drive LED light-bar.

Note (3) $P_L = I_L \times V_L$ (Without LED converter transfer efficiency)

Note (4) The lifetime of LED is defined as the time when it continues to operate under the conditions at $T_a = 25 \pm 2^\circ\text{C}$ and $I_L = 22\text{ mA}$ (Per EA) until the brightness becomes $\leq 50\%$ of its original value.

3.8 Signal Timing Specifications

| Signal | Item | Symbol | Min. | Typ. | Max. | Unit |
|--------|----------------------------------|--------|------|-------|------|------|
| DCLK | Frequency | 1/Tc | - | 159.4 | - | MHz |
| DE | Vertical Total Time | TV | 1981 | 1981 | 1982 | TH |
| | Vertical Active Display Period | TVD | - | 1920 | - | TH |
| | Vertical Front Porch Period | TVFP | 35 | 35 | 36 | TH |
| | Vsync pulse width | TVPW | 1 | 1 | 1 | TH |
| | Vertical Back Porch Period | TVBP | | 25 | | TH |
| | Horizontal Total Time | TH | 1275 | 1341 | 1342 | Tc |
| | Horizontal Active Display Period | THD | - | 1200 | - | Tc |
| | Horizontal Front Porch Period | THFP | 42 | 80 | 81 | Tc |
| | Horizontal pulse width | THPW | 1 | 1 | 1 | Tc |
| | Horizontal Back Porch Period | THBP | 32 | 60 | 60 | Tc |
| | MIPI Data frequency | FDATA | 955 | 999 | 1000 | MHz |

Note1: DCLK = TV x TH x frame rate, and frame rate = 60Hz.

Note 2: The CABC and CE function were disabled.

3.9 MIPI Interface DC/AC Characteristic

3.9.1 MIPI Interface DC characteristic

| Parameter | Symbol | Conditions | Specification | | | UNIT |
|---|---------------|--|---------------|-----|------|------|
| | | | MIN | TYP | MAX | |
| MIPI digital operation current | I_{VCCIF} | $V_{CC}=V_{CC_IF}=1.5V$, Data Rate=500Mbps, | - | - | 24 | mA |
| MIPI digital stand-by current | $I_{VCCIFST}$ | V_{CC_IF} input current. All input signal are stopped. | - | 200 | - | uA |
| MIPI Characteristics for High Speed Receiver | | | | | | |
| Single-ended input low voltage | V_{ILHS} | | -40 | - | - | mV |
| Single-ended input high voltage | V_{IHHS} | | - | - | 460 | mV |
| Common-mode voltage | V_{CMRXDC} | | 155 | - | 330 | mV |
| Differential input impedance | Z_{ID} | | 80 | 100 | 125 | ohm |
| Differential input high threshold | V_{IDTH} | | | - | 70 | mV |
| Differential input low threshold | V_{IDTL} | | 70 | - | - | mV |
| MIPI Characteristics for Low Power Mode | | | | | | |
| Pad signal voltage range | V_I | | -50 | - | 1350 | mV |
| Ground shift | V_{GNDSH} | | -50 | - | 50 | mV |
| Output low level | V_{OL} | | -150 | | 150 | mV |
| Output high level | V_{OH} | | 1.1 | 1.2 | 1.3 | V |

Note 1) $V_{DD}=2.7V$ to $3.6V$, $AV_{DD}=7V$ to $10V$, $GND=AGND=0V$, $T_A=-20$ to $+85^{\circ}C$

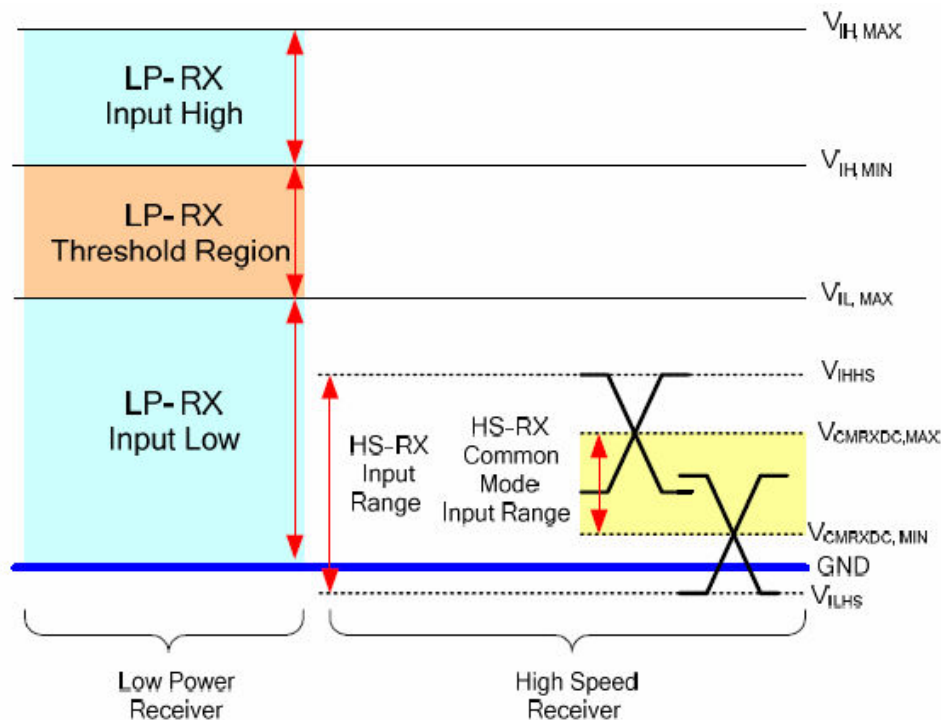


Figure :MIPI DC Diagram

3.9.2 MIPI AC Characteristic

3.9.2.1 LP Transmission

(VDD= 2.7V to 3.6V, AVDD= 7V to 10V, GND=AGND= 0V, TA= -20 to +85°C)

| Parameter | Symbol | Specification | | | UNIT |
|--|---------------------|---------------|-----|-----|------|
| | | MIN | TYP | MAX | |
| 15%-85% rise time and fall time | T_{RLP} / T_{FLP} | - | - | 25 | ns |
| Pulse width of the LP exclusive-OR clock | $T_{LP-PULSE-TX}$ | -50 | - | - | ns |
| Period of the LP exclusive-OR clock | $T_{LP-PER-TX}$ | 100 | | | ns |

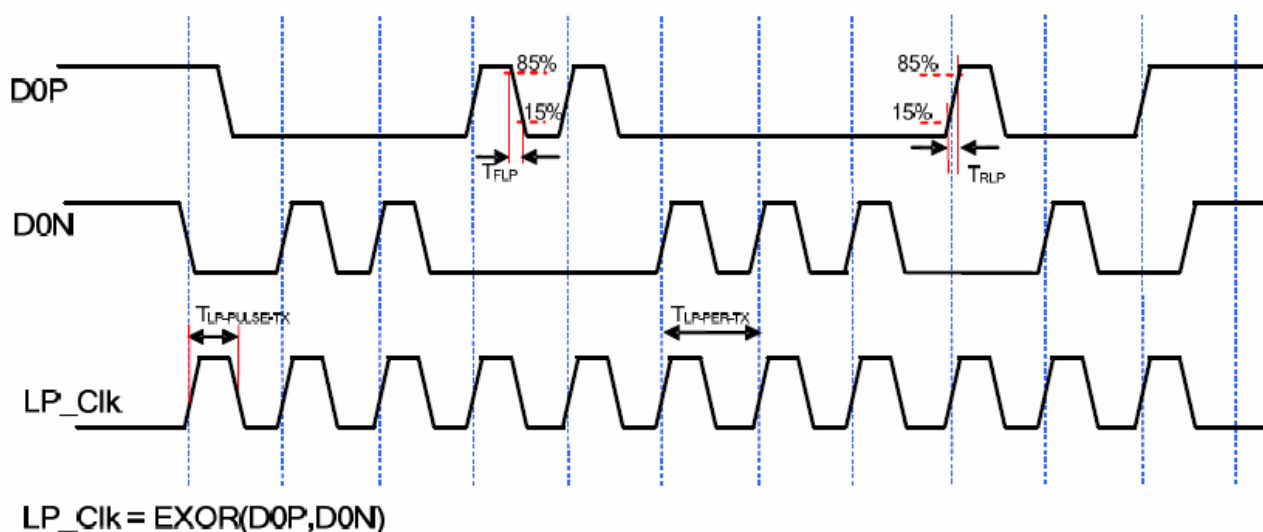


Figure :LP Transmitter Timing Definitions

3.9.3 High Speed Transmission

3.9.3.1 Data-Clock Timing Specifications

(VDD= 2.7V to 3.6V, AVDD= 7V to 10V, GND=AGND= 0V, TA= -20 to +85°C)

| Parameter | Symbol | Specification | | | UNIT |
|--------------------------|-------------|---------------|-----|------|-------------|
| | | MIN | TYP | MAX | |
| UI instantaneous | UI_{INST} | 1.0 | - | 12.5 | ns |
| Data to Clock Setup Time | T_{SETUP} | 0.25 | - | - | UI_{INST} |
| Data to Clock Hold Time | T_{HOLD} | 0.25 | - | - | UI_{INST} |

Note:

Data to clock setup time/ hold time cannot reach those listed in above “Data-Clock Timing Specifications” may cause abnormal display.

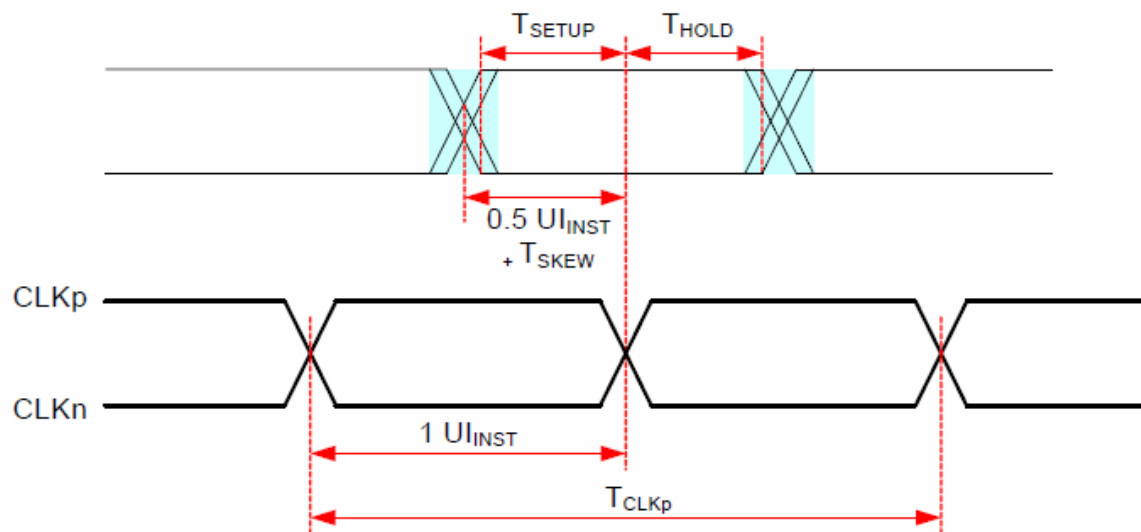


Figure : Data to Clock Timing Definitions

3.9.3.2 High-Speed Data Transmission in Bursts

3.9.3.2.1 High-Speed Data Transmission Operation Timing Parameters

(VDD= 2.7V to 3.6V, AVDD= 7V to 10V, GND=AGND= 0V, TA= -20 to +85°C)

| Parameter | Symbol | Specification | | | UNIT |
|---|-------------------------|---------------|-----|----------|------|
| | | MIN | TYP | MAX | |
| Time to drive LP-00 to prepare for HS transmission | $T_{\text{HS-PREPARE}}$ | 40+4UI | - | 85+6UI | ns |
| Time from start of tHS-TRAIL or tCLK-TRAIL period to start of LP-11 state | T_{EOT} | - | - | 105+12UI | ns |
| Time to enable Data Lane receiver line termination measured from when Dn cross VIL,MAX | $T_{\text{HS-TERM-EN}}$ | - | - | 35+4UI | ns |
| Time to drive flipped differential state after last payload data bit of a HS transmission burst | $T_{\text{HS-TRAIL}}$ | 60+4UI | - | - | ns |
| Time-out at RX to ignore transition period of EoT | $T_{\text{HS-SKIP}}$ | 40 | - | 55+4UI | ns |
| Time to drive LP-11 after HS burst | $T_{\text{HS-EXIT}}$ | 100 | - | - | ns |
| Length of any Low-Power state period | T_{LPX} | 50 | - | - | ns |
| Sync sequence period | $T_{\text{HS-SYNC}}$ | - | 8UI | - | ns |
| Minimum lead HS-0 drive period before the Sync sequence | $T_{\text{HS-ZERO}}$ | 105+6UI | - | - | ns |

Note:

1. The minimum value depends on the bit rate. Implementations should ensure proper operation for all the supported bit rates.
2. UI means Unit Interval, equal to one half HS clock period on the Clock Lane.
3. T_{LPX} is an internal state machine timing reference. Externally measured values may differ slightly from the specified values due to asymmetrical rise and fall times.

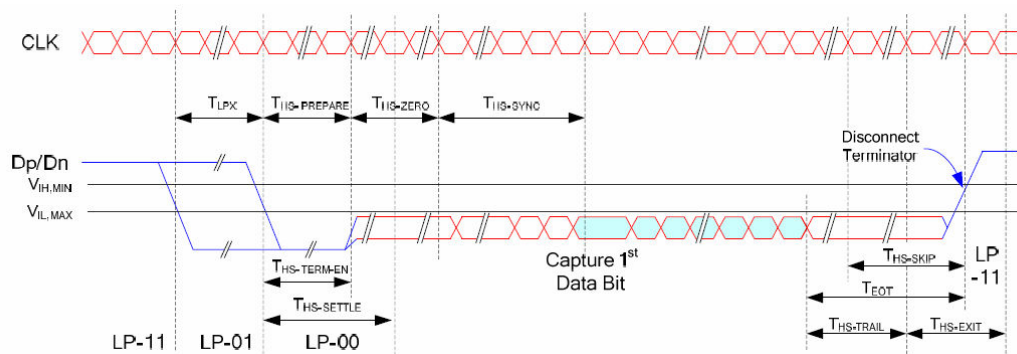


Figure : High-Speed Data Transmission in Bursts

3.9.3.3 High-Speed Clock Transmission

3.9.3.3.1 Switching the Clock Lane Operation Timing Parameters

(VDD= 2.7V to 3.6V, AVDD= 7V to 10V, GND=AGND= 0V, TA= -20 to +85°C)

| Parameter | Symbol | Specification | | | UNIT |
|--|--|---------------|-----|-----|------|
| | | MIN | TYP | MAX | |
| Time that the transmitter shall continue sending HS clock after the last associated Data Lane has transitioned to LP mode | T _{CLK-POST} | 60+52UI | - | - | ns |
| Detection time that the clock has stopped toggling | T _{CLK-MISS} | - | - | 60 | ns |
| Time to drive LP-00 to prepare for HS clock transmission | T _{CLK-PREPARE} | 38 | - | 95 | ns |
| Minimum lead HS-0 drive period before starting Clock | T _{CLK-PREPARE} + T _{CLK-ZERO} | 300 | - | - | ns |
| Time to enable Clock Lane receiver line termination measured from when Dn cross VIL,MAX | T _{HS-TERM-EN} | | | 38 | ns |
| Minimum time that the HS clock must be set prior to any associated data lane beginning the transmission from LP to HS mode | T _{CLK-PRE} | 8 | - | - | UI |
| Time to drive HS differential state after last payload clock bit of a HS transmission burst | T _{CLK-TRAIL} | 60 | - | - | ns |

Note:

The DSI host processor shall support continuous clock on the Clock Lane for NT chip that require it, so the host processor needs to keep the HS serial clock running.

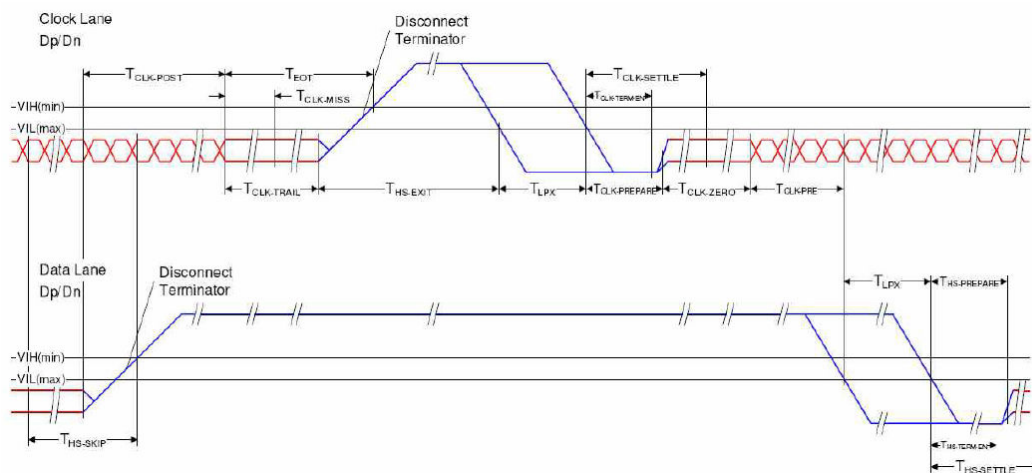
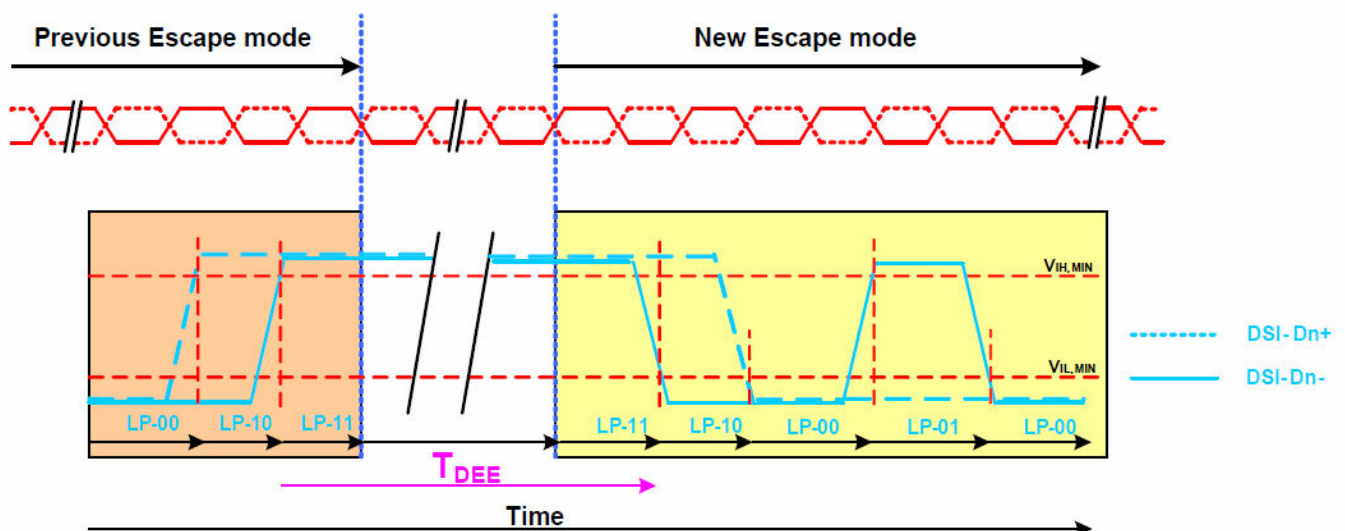


Figure : Switching the Clock Lane between Clock Transmission and Low-Power Mode

3.9.3.4 LP11 timing request between data transformation

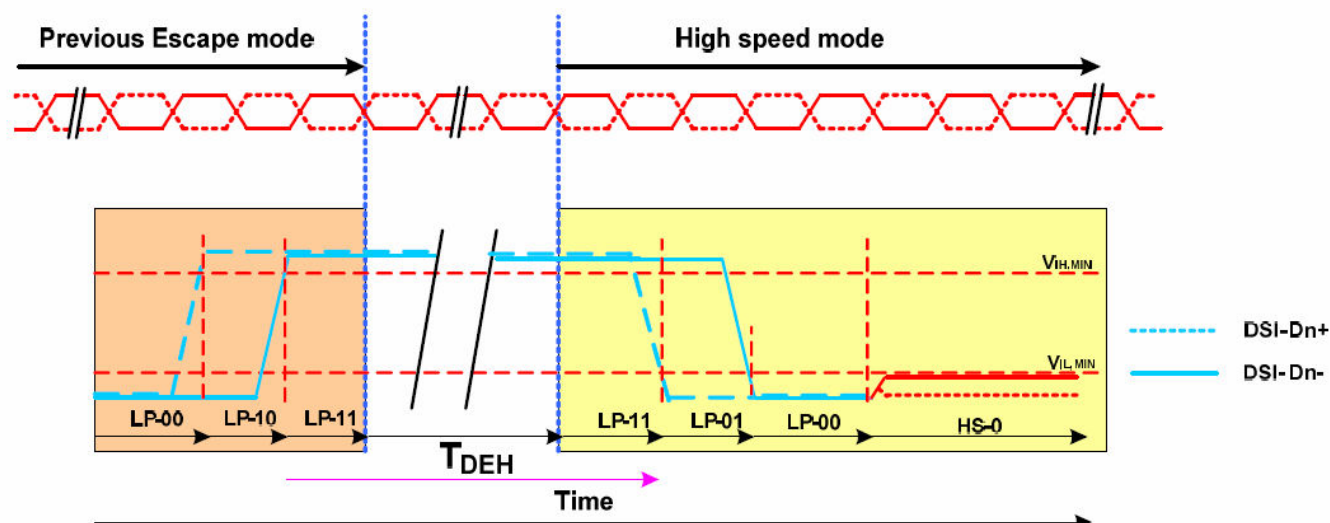
When Clock lane of DSI TX chip always keeps High speed mode, then Clock lane never go back to Low power mode. If Date lane of TX chip needs to transmit the next new data transmission or sequence, after the end of Low power mode or High speed mode. Then TX chip needs to keep LP-11 stop state before the next new data transmission, no matter in Low power mode or High speed mode. The LP-11 minimum timing is required for RX chip in the following 9 conditions, include of LP - LP, LP - HS, HS - LP, and HS – HS. This rule is suitable for short or long packet between TX and RX data transmission.

(1) Timing between LP - LP command



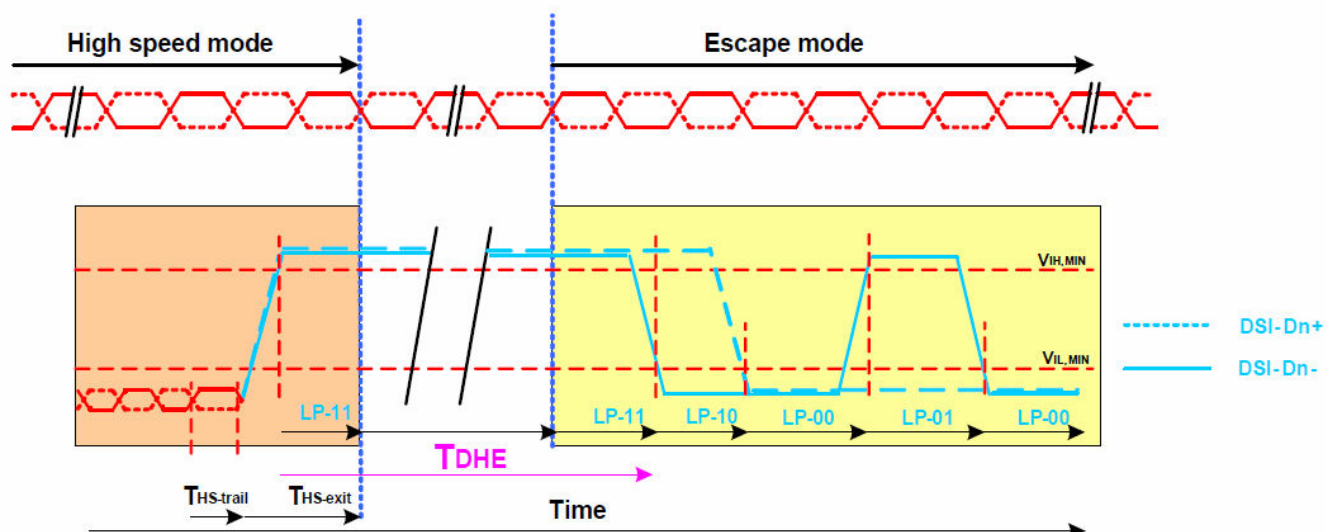
| Parameter | Symbol | Specification | | | UNIT |
|---|-----------|---------------|-----|-----|------|
| | | MIN | TYP | MAX | |
| LP-11 delay to a start of the new Escape Mode Entry | T_{DEE} | 150 | - | - | ns |

(2) Timing between LP - HS command



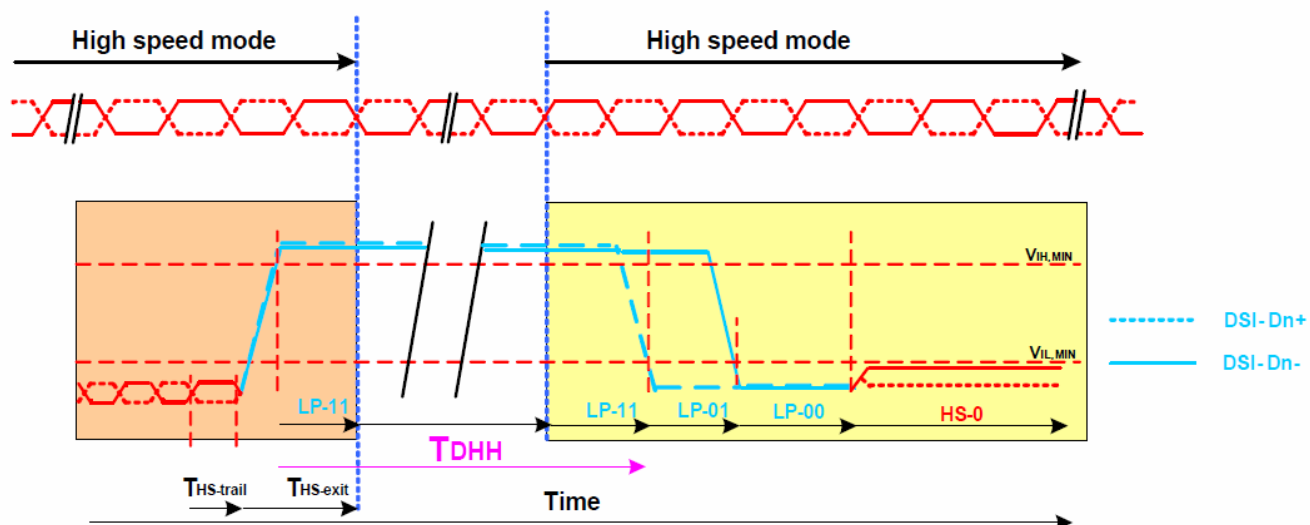
| Parameter | Symbol | Specification | | | UNIT |
|--|-----------|---------------|-----|-----|------|
| | | MIN | TYP | MAX | |
| LP-11 delay to a start of the Entering High Speed Mode | T_{DEH} | Max(150,32UI) | - | - | ns |

(3) Timing between HS - LP command



| Parameter | Symbol | Specification | | | UNIT |
|---|-----------|---------------|-----|-----|------|
| | | MIN | TYP | MAX | |
| LP-11 delay to a start of the Escape Mode Entry | T_{DHE} | Max(150,32UI) | - | - | ns |

(4) Timing between HS - HS command



| Parameter | Symbol | Specification | | | UNIT |
|--|-----------|---------------|-----|-----|------|
| | | MIN | TYP | MAX | |
| LP-11 delay to a start of the Entering High Speed Mode | T_{DHH} | Max(150,32UI) | - | - | ns |

3.10 MIPI interface (Mobile Industry Processing Interface)

The Display Serial Interface standard defines protocols between a host processor and peripheral devices that adhere to MIPI Alliance standards for mobile device interfaces. The DSI standard builds on existing standards by adopting pixel formats and command set defined in MIPI Alliance standards. DSI-compliant peripherals support either of two basic modes of operation: Command Mode and Video Mode. Which mode is used depends on the architecture and capabilities of the peripheral. The mode definitions reflect the primary intended use of DSI for display interconnect, but are not intended to restrict DSI from operating in other applications.

Command Mode refers to operation in which transactions primarily take the form of sending commands and data to a peripheral, such as a display module, that incorporates a display controller. The display controller may include local registers. Systems using Command Mode write to, and read from the registers. The host processor indirectly controls activity at the peripheral by sending commands, parameters and data to the display controller. The host processor can also read display module status information. Command Mode operation requires a bidirectional interface.

Video Mode refers to operation in which transfers from the host processor to the peripheral take the form of a real-time pixel stream. In normal operation, the display module relies on the host processor to provide image data at sufficient bandwidth to avoid flicker or other visible artifacts in the displayed image. Video information should only be transmitted using High Speed Mode. To reduce complexity and cost, systems that only operate in Video Mode may use a unidirectional data path.

Note: The NT51021 IC only supports Video Mode operation.

3.10.1 MIPI Lane Configuration

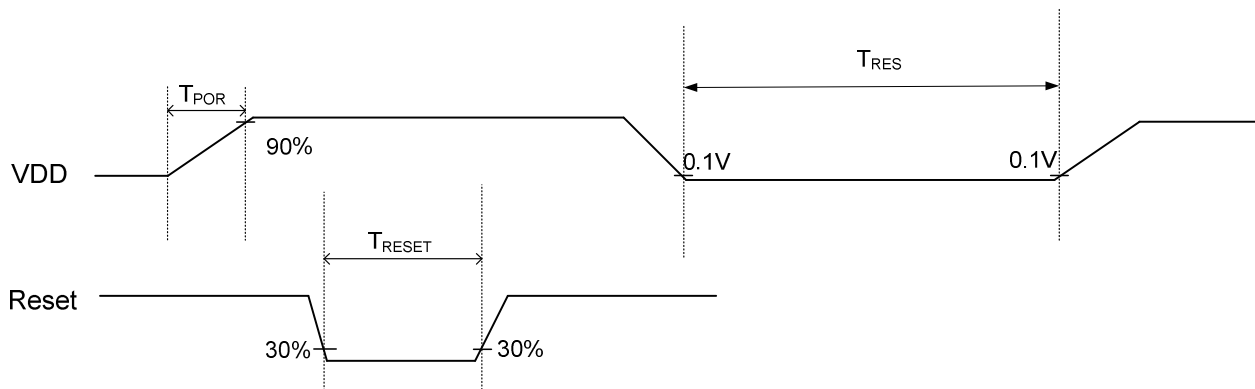
| | MCU (Master) | Display Module (Slave) |
|---------------|--|------------------------|
| Clock Lane+/- | Unidirectional Lane ■ Clock Only ■ Escape Mode(ULPS Only) | |
| Data Lane0+/- | Unidirectional Lane ■ Forward High-Speed ■ Forward Escape Mode ■ Forward LPDT | |
| Data Lane1+/- | Unidirectional ■ Forward High speed | |
| Data Lane2+/- | Unidirectional ■ Forward High speed | |
| Data Lane3+/- | Unidirectional ■ Forward High speed | |

The connection between host device and display module is as reference.

3.11 Input AC Characteristic

a. VDD/GRB AC characteristic:

VDD= 3..3V, GND=AGND= 0V, TA= -20 to +85°C)



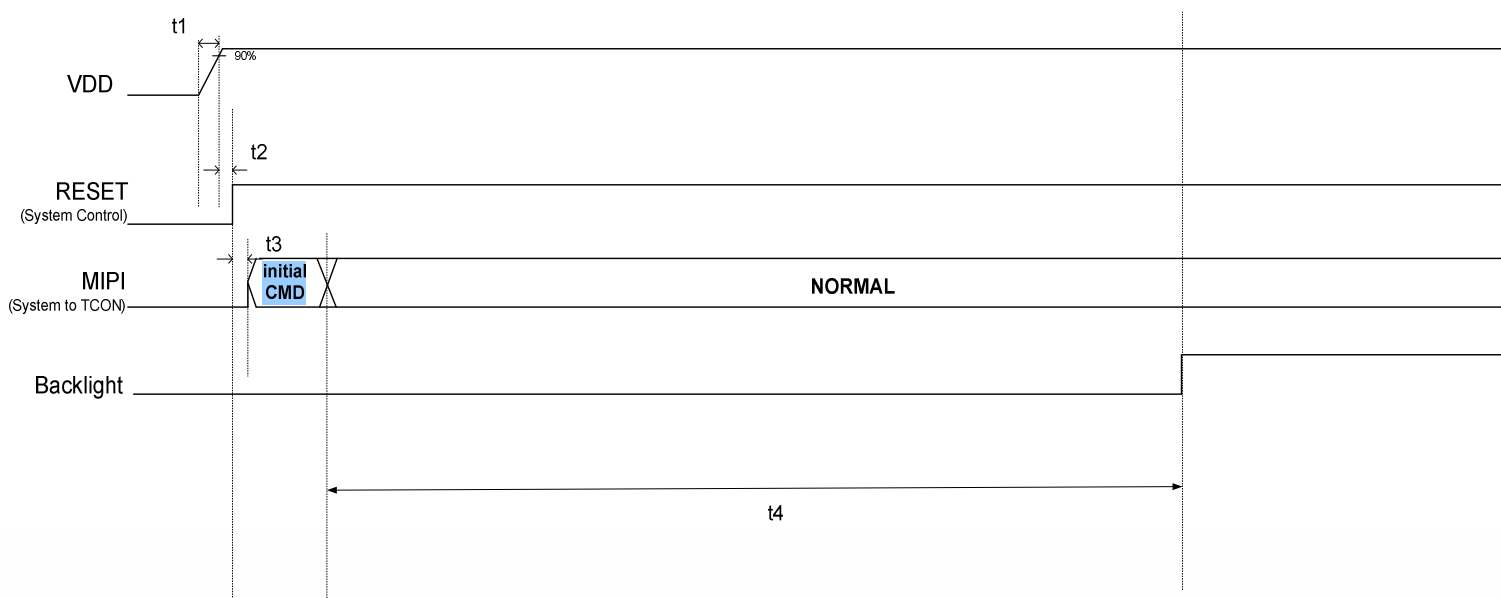
| Parameter Symbol | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|----------------------------|--------------------|------|------|------|------|--------------------|
| VDD power source slew time | T _{POR} | - | - | 20 | ms | From 0V to 90% VDD |
| RESET active pulse width | T _{RESET} | 1 | - | - | ms | VDD=3.3V |
| VDD resettle time | T _{RES} | 1 | - | - | s | |

3.12 POWER ON/OFF SEQUENCE

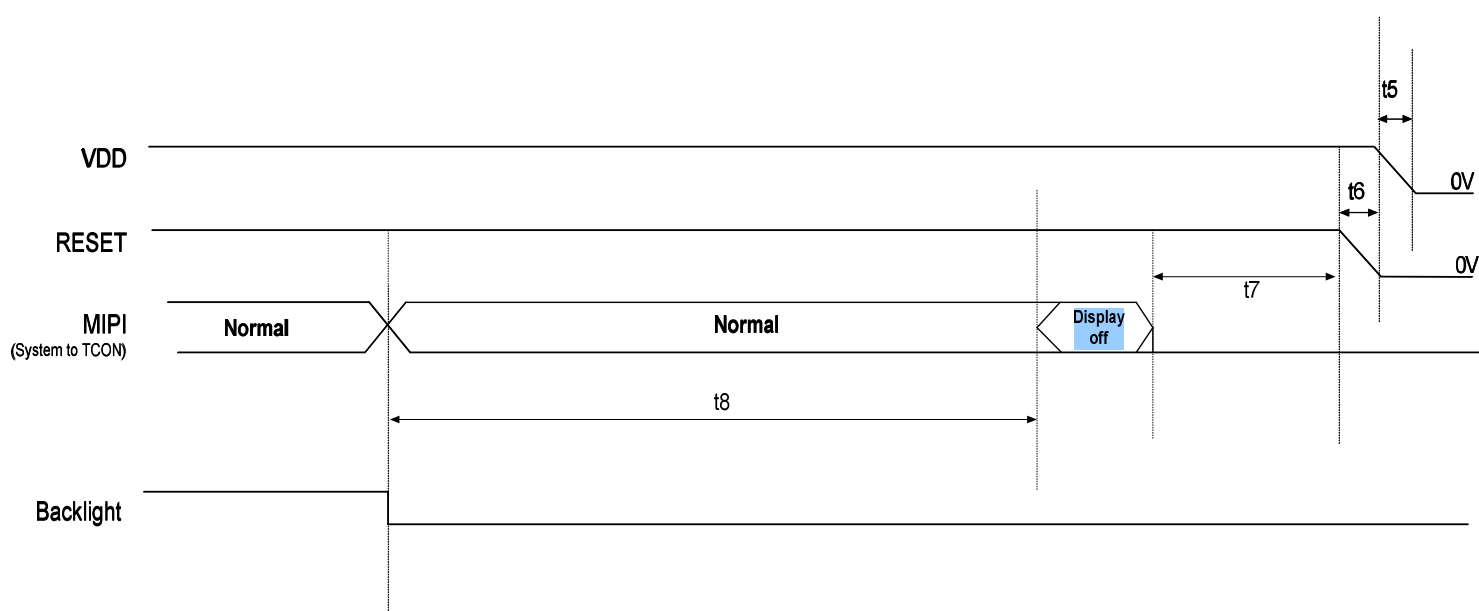
The power sequence specifications are shown as the following table and diagram.

a. Power on Timing Sequence:

VDD=3.0 to 3.6V



| Symbol | Value | | | Unit | Remark |
|--------|------------|------|----------|------|--------|
| | Min. | Typ. | Max. | | |
| t1 | - | - | 2 | ms | |
| t2 | 5 | - | - | ms | |
| t3 | 20 | - | - | ms | |
| t4 | 100 | - | - | ms | |

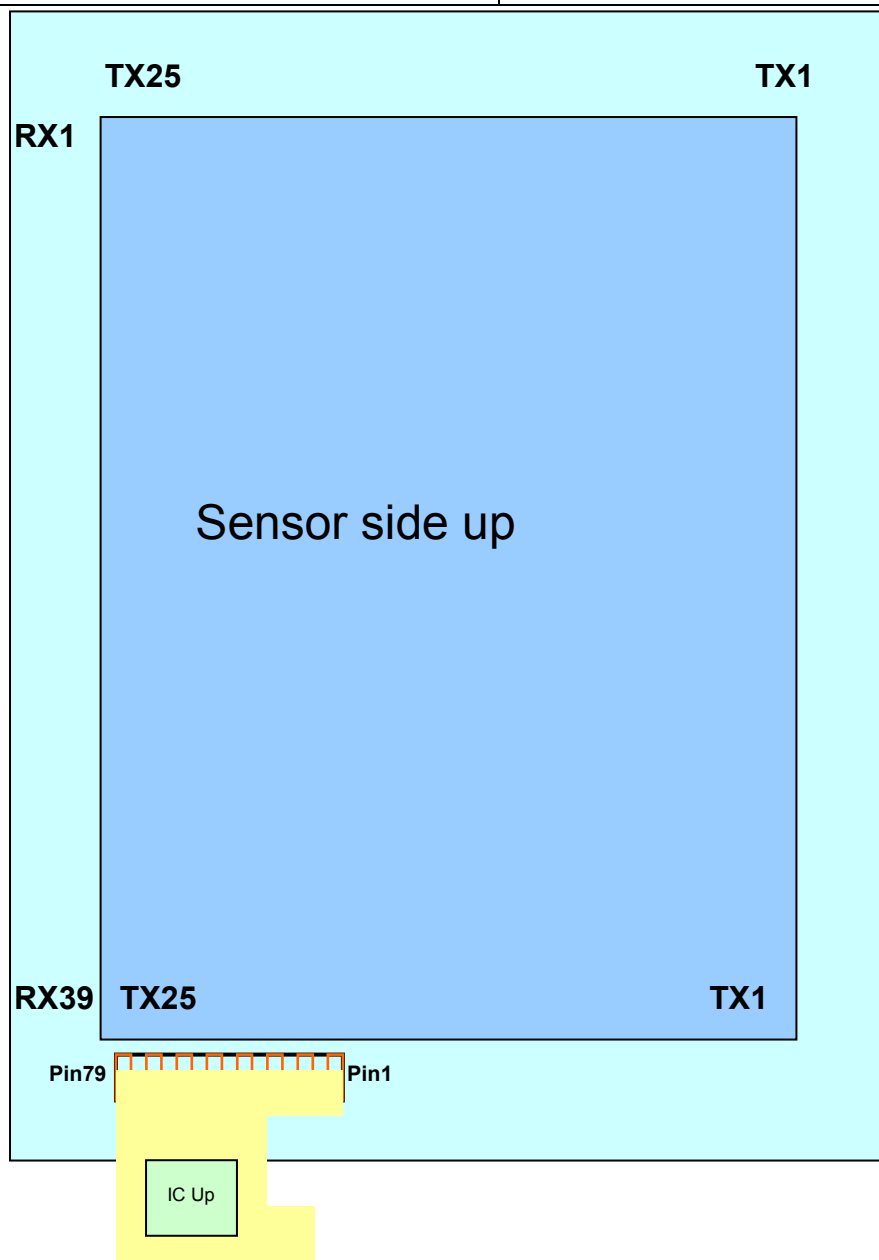
b. Power off:
VDD=3.0 to 3.6V.


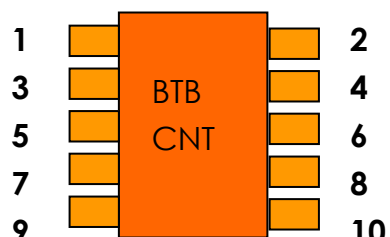
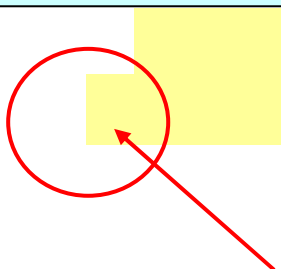
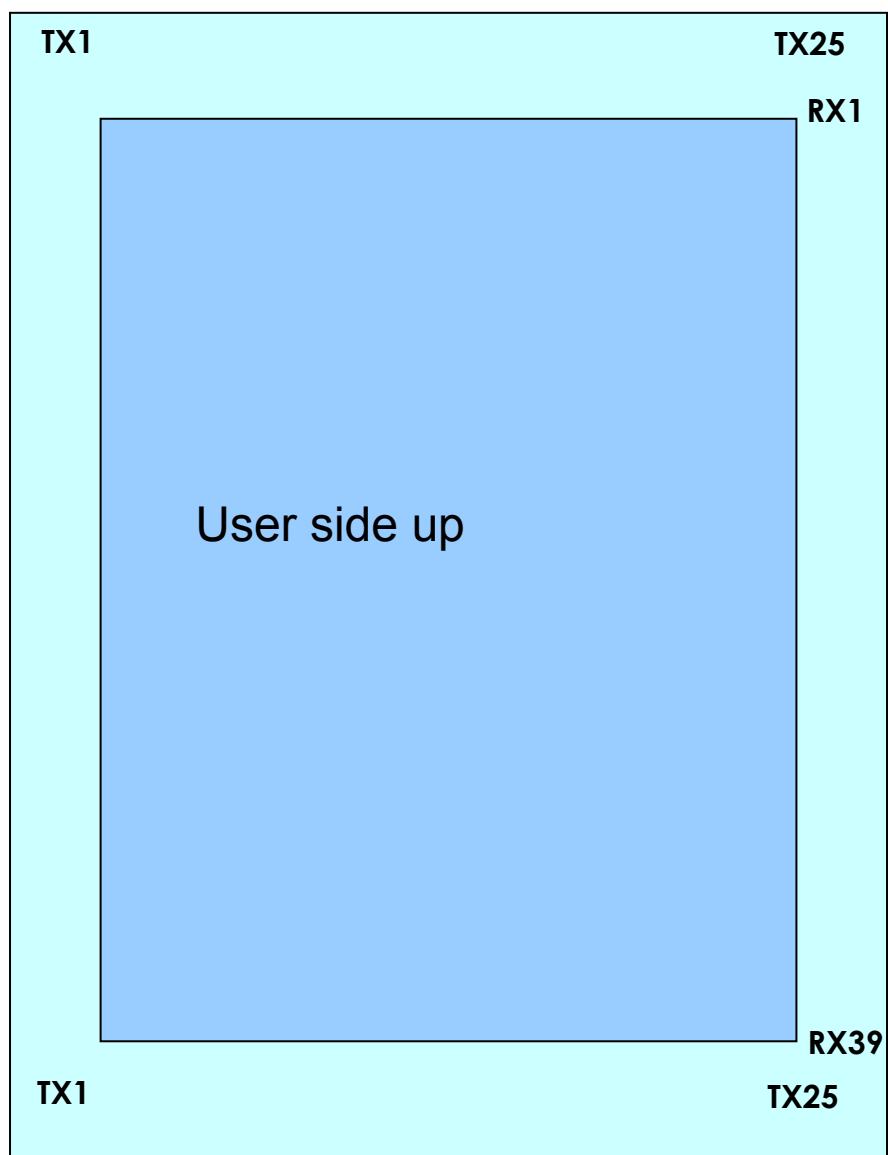
| Symbol | Value | | | Unit | Remark |
|--------|------------|------|------|------|--------|
| | Min. | Typ. | Max. | | |
| t5 | 0 | - | - | ms | |
| t6 | 0 | - | - | ms | |
| t7 | 100 | - | - | ms | |
| t8 | 20 | - | - | ms | |

4. Electrical Specifications of TPM

4.1 General Specifications of TPM

| | |
|--------------------------------|--|
| TP Technology | Projected Capacitive Multi-Touch Panel |
| Sensing technology | Projected mutual |
| Touch Structure | WIS |
| Touch Channels (X - Y) | 25-39 |
| Sensor Pitch (X - Y) | X 4.3456mm/Y 4.4415mm |
| FPC Golden Finger shape | Follow : DF37B-10DP-0.4V(51) HRS |
| Supply Voltage | VDD 3.3V |





4.2 Electrical Characteristics of TPM

| Item | Spec | | | | | | | | | | | | | | | | | | | | | | |
|--|--|---------|--|---|---------|---|-----|---|-------------|---|-----------------|---|----------------|---|---------------------|---|---------|---|-----|---|-----|----|--------------|
| Supply Voltage | VDD 3.3V | | | | | | | | | | | | | | | | | | | | | | |
| Interface | I2C | | | | | | | | | | | | | | | | | | | | | | |
| Chipset | Nova NT11003_QFN88B | | | | | | | | | | | | | | | | | | | | | | |
| Interface Connector to system | DF37B-10DP-0.4V(51) HRS | | | | | | | | | | | | | | | | | | | | | | |
| Interface Connector Pin Assignment (BTB CNT) | <table border="1"> <thead> <tr> <th>Pin no.</th><th></th></tr> </thead> <tbody> <tr><td>1</td><td>ESD_GND</td></tr> <tr><td>2</td><td>GND</td></tr> <tr><td>3</td><td>VDDIO(1.8V)</td></tr> <tr><td>4</td><td>I2C Clock (SCK)</td></tr> <tr><td>5</td><td>I2C Data (SDA)</td></tr> <tr><td>6</td><td>I2C Interrupt (INT)</td></tr> <tr><td>7</td><td>TP_Sync</td></tr> <tr><td>8</td><td>GND</td></tr> <tr><td>9</td><td>RST</td></tr> <tr><td>10</td><td>VDDIN (3.3V)</td></tr> </tbody> </table> | Pin no. | | 1 | ESD_GND | 2 | GND | 3 | VDDIO(1.8V) | 4 | I2C Clock (SCK) | 5 | I2C Data (SDA) | 6 | I2C Interrupt (INT) | 7 | TP_Sync | 8 | GND | 9 | RST | 10 | VDDIN (3.3V) |
| Pin no. | | | | | | | | | | | | | | | | | | | | | | | |
| 1 | ESD_GND | | | | | | | | | | | | | | | | | | | | | | |
| 2 | GND | | | | | | | | | | | | | | | | | | | | | | |
| 3 | VDDIO(1.8V) | | | | | | | | | | | | | | | | | | | | | | |
| 4 | I2C Clock (SCK) | | | | | | | | | | | | | | | | | | | | | | |
| 5 | I2C Data (SDA) | | | | | | | | | | | | | | | | | | | | | | |
| 6 | I2C Interrupt (INT) | | | | | | | | | | | | | | | | | | | | | | |
| 7 | TP_Sync | | | | | | | | | | | | | | | | | | | | | | |
| 8 | GND | | | | | | | | | | | | | | | | | | | | | | |
| 9 | RST | | | | | | | | | | | | | | | | | | | | | | |
| 10 | VDDIN (3.3V) | | | | | | | | | | | | | | | | | | | | | | |
| Support OS | Android | | | | | | | | | | | | | | | | | | | | | | |
| FPC | 2 Layers; 1/3 oz | | | | | | | | | | | | | | | | | | | | | | |

4.3 TPM Pin Assignment

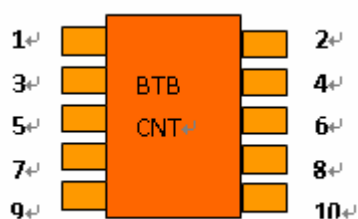
4.3.1 Sensor & FPCa Pin Assignment

金手指端 Pin Assignment

| pin # | pin assignment | pin # | pin assignment | pin # | pin assignment | pin # | pin assignment |
|-------|----------------|-------|----------------|-------|----------------|-------|----------------|
| 1 | GND | 22 | TX20 | 43 | RX37 | 64 | RX16 |
| 2 | GND | 23 | TX21 | 44 | RX36 | 65 | RX15 |
| 3 | TX1 | 24 | TX22 | 45 | RX35 | 66 | RX14 |
| 4 | TX2 | 25 | TX23 | 46 | RX34 | 67 | RX13 |
| 5 | TX3 | 26 | TX24 | 47 | RX33 | 68 | RX12 |
| 6 | TX4 | 27 | TX25 | 48 | RX32 | 69 | RX11 |
| 7 | TX5 | 28 | NA | 49 | RX31 | 70 | RX10 |
| 8 | TX6 | 29 | NA | 50 | RX30 | 71 | RX9 |
| 9 | TX7 | 30 | NA | 51 | RX29 | 72 | RX8 |
| 10 | TX8 | 31 | NA | 52 | RX28 | 73 | RX7 |
| 11 | TX9 | 32 | ESD_GND | 53 | RX27 | 74 | RX6 |
| 12 | TX10 | 33 | ESD_GND | 54 | RX26 | 75 | RX5 |
| 13 | TX11 | 34 | ESD_GND | 55 | RX25 | 76 | RX4 |
| 14 | TX12 | 35 | NA | 56 | RX24 | 77 | RX3 |

| | | | | | | | |
|----|------|----|------|----|------|----|-----|
| 15 | TX13 | 36 | NA | 57 | RX23 | 78 | RX2 |
| 16 | TX14 | 37 | NA | 58 | RX22 | 79 | RX1 |
| 17 | TX15 | 38 | NA | 59 | RX21 | | |
| 18 | TX16 | 39 | GND | 60 | RX20 | | |
| 19 | TX17 | 40 | GND | 61 | RX19 | | |
| 20 | TX18 | 41 | RX39 | 62 | RX18 | | |
| 21 | TX19 | 42 | RX38 | 63 | RX17 | | |

(b) Connector Pin Assignment



| pin # | pin assignment |
|-------|----------------|
| 1 | ESD_GND |
| 2 | GND |
| 3 | VDDIO(1.8V) |
| 4 | SCK |
| 5 | SDA |
| 6 | INT |
| 7 | TP_Sync |
| 8 | GND |
| 9 | RST |
| 10 | VDDIN(3.3V) |

4.3.2 TP Performance

| Test parameter | Spec |
|--------------------------------|---|
| Multi-touch | 10 point |
| Report Rate (continuous) | <16.7ms |
| Response time (idle to active) | <35ms |
| Linearity with 5mm finger | < 1mm on X, Y and Diagonal at 5mm/sec and 50mm/sec speed |
| Accuracy with 5mm finger | < 1mm tested on 13 points by touching each point 10 times |
| Finger Separation | 2 fingers when distance is >12mm |
| Jitter | < 1mm with stationary contact for 5 secs |
| Noise suppression capability | 40Vpp common mode noise with 50-500KHz noise requency with 5 σ and 22 σ |

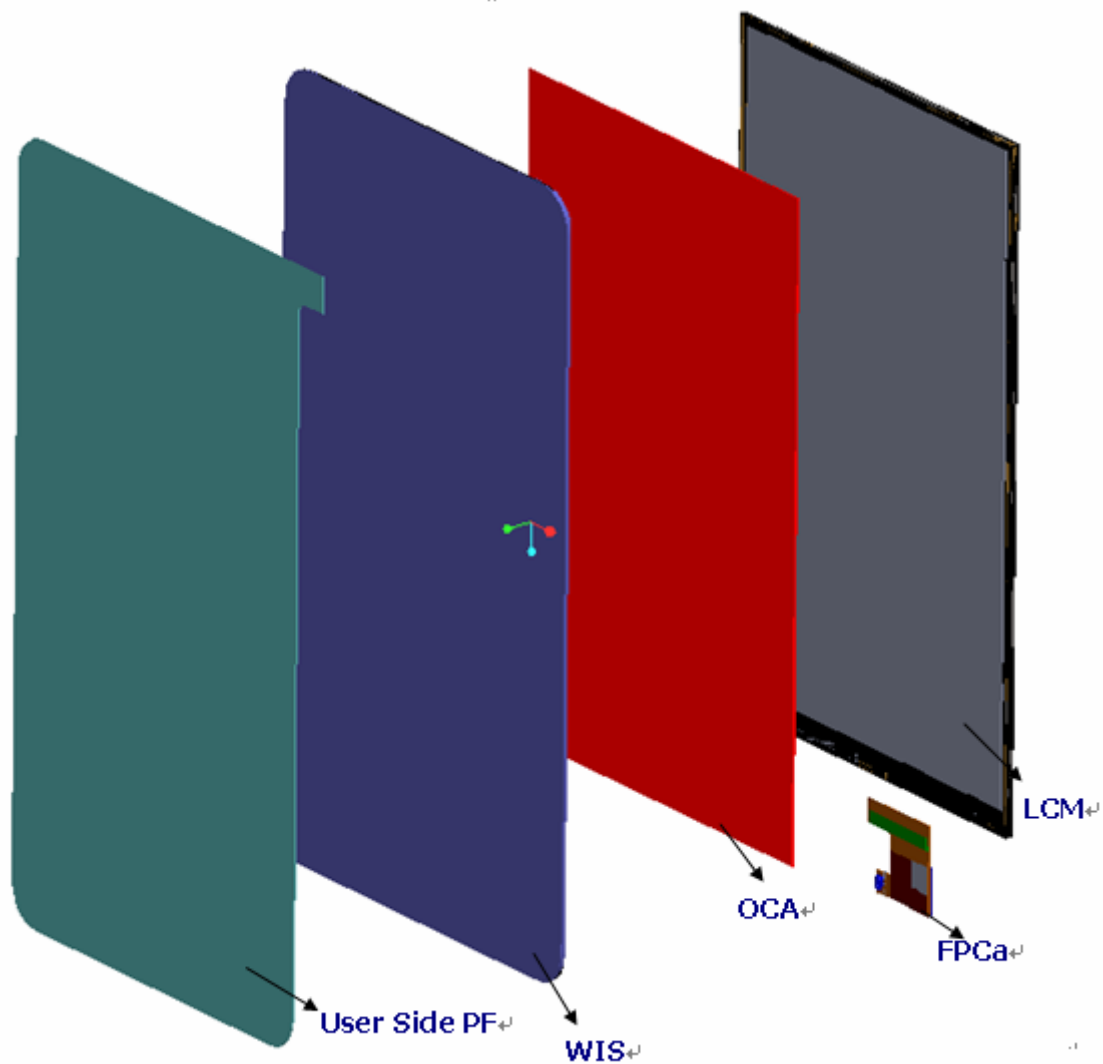
5. Mechanical Specifications of TDM

5.1 Mechanical Specifications of LCM

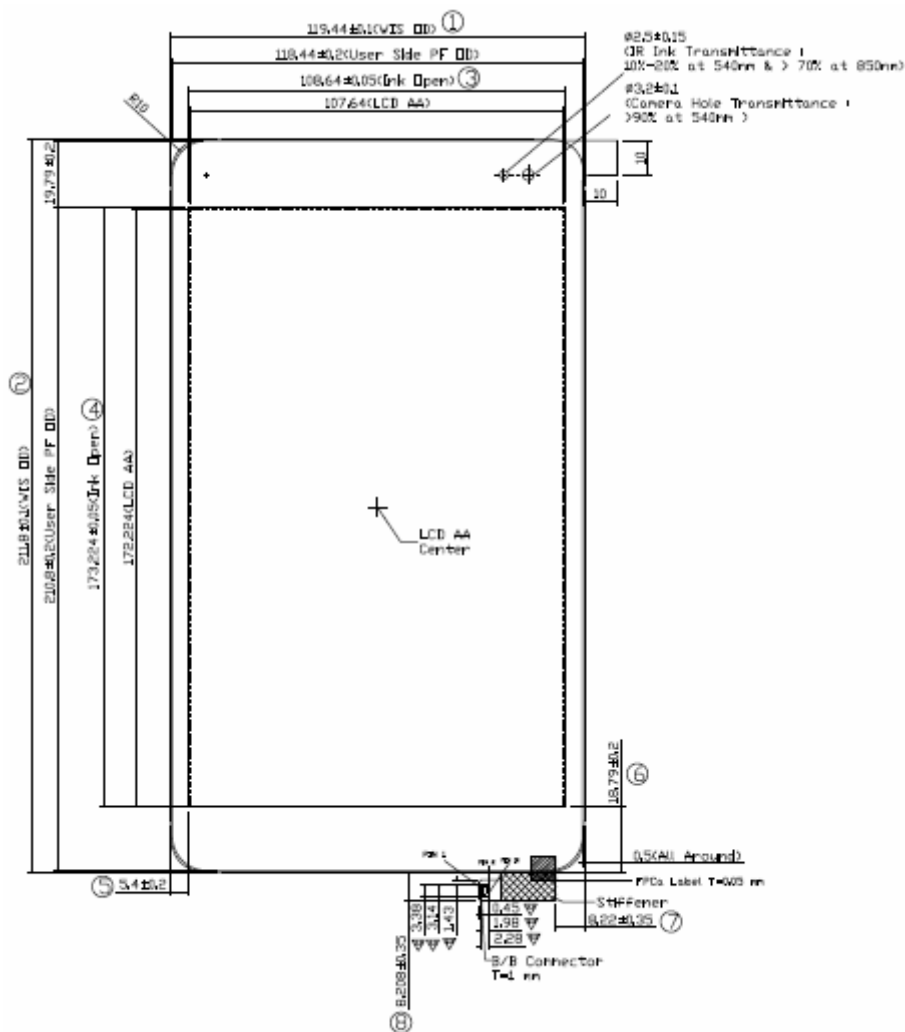
| Item | | Min. | Typ. | Max. | Unit | Note |
|--------------|----------------|---------|---------|---------------------------------|------|--------------|
| Module Size | Horizontal (H) | 114.3 | 114.6 | 114.9 | mm | Module Size |
| | Vertical (V) | 184.3 | 184.6 | 184.9 | mm | |
| | Thickness (T) | | | 2.15(w/o FPCA) 3.65(w/ FPCA) | mm | |
| CF Polarizer | Horizontal | 110.14 | 110.44 | 110.74 | mm | CF Polarizer |
| | Vertical | 175.32 | 175.62 | 175.92 | mm | |
| Active Area | Horizontal | 107.59 | 107.64 | 107.69 | mm | Active Area |
| | Vertical | 172.174 | 172.224 | 172.274 | mm | |
| Weight | | - | - | 90 | g | |

Note (1) Please refer to the attached drawings for more information of front and back outline dimensions.

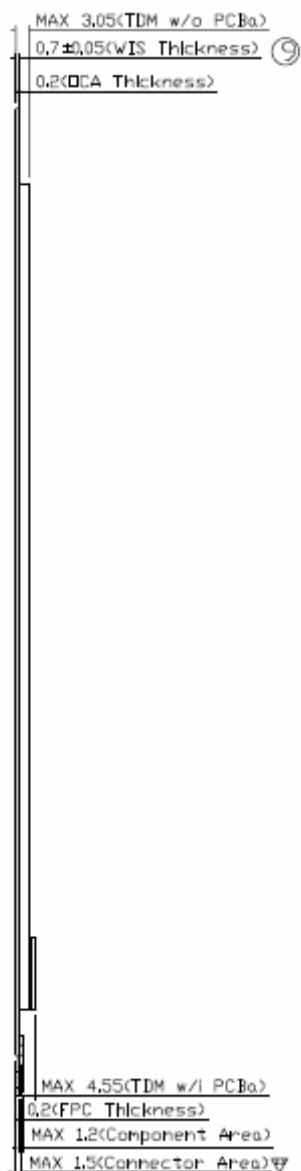
5.2 TDM Explosion Figure

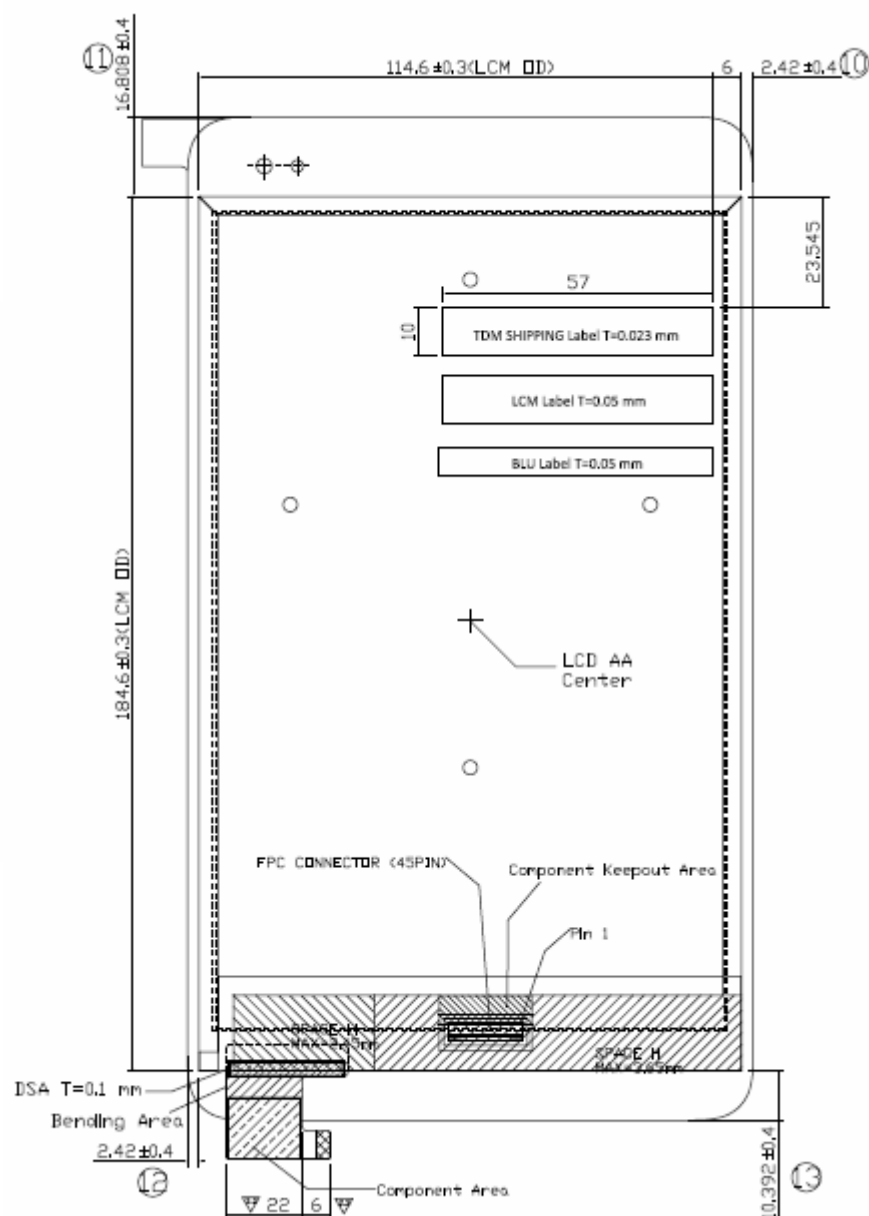


5.3 TDM Drawing



PRODUCT SPECIFICATION





6. Absolute Maximum Ratings of LCM

6.1 Absolute Ratings of Environment

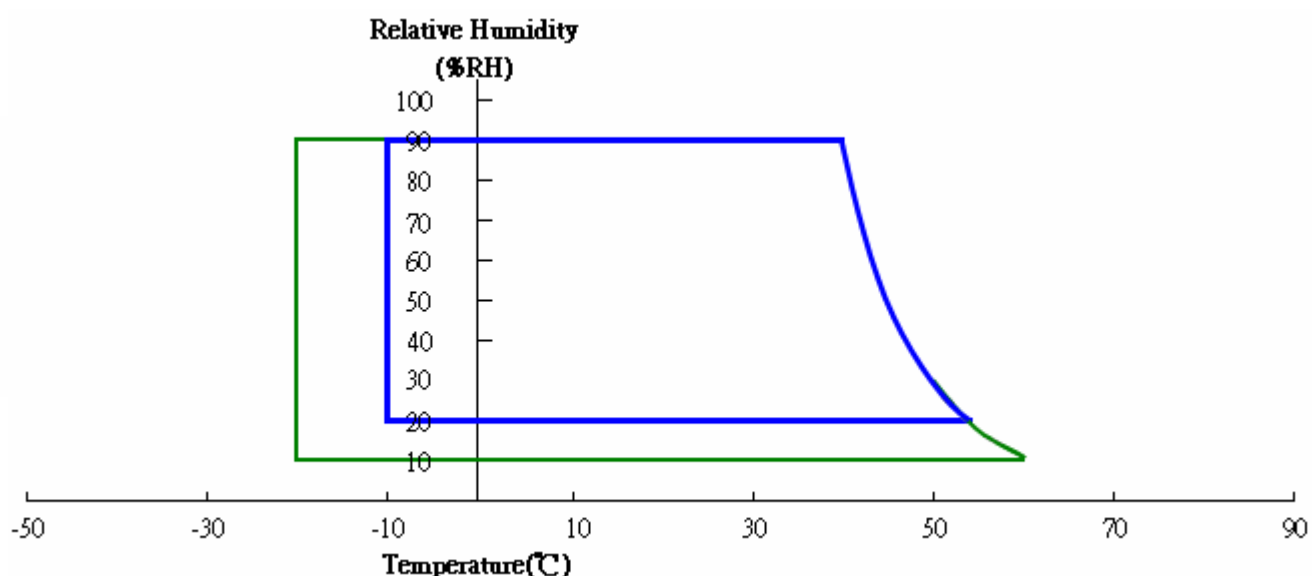
| Item | Symbol | Value | | Unit | Note |
|-------------------------------|-----------------|-------|------|------|----------|
| | | Min. | Max. | | |
| Storage Temperature | T _{ST} | -20 | +60 | °C | (1) |
| Operating Ambient Temperature | T _{OP} | -10 | +50 | °C | (1), (2) |

Note (1) (a) 90 %RH Max.

(b) Wet-bulb temperature should be 39 °C Max.

(c) No condensation.

Note (2) The temperature of panel surface should be -10 °C min. and 60 °C max.



6.2 Electrical Absolute Ratings

6.2.1 TFT LCD Module

| Item | Symbol | Value | | Unit | Note |
|----------------------|--------|-------|------|------|------|
| | | Min. | Max. | | |
| Power Supply Voltage | VDD | +2.7 | +3.6 | V | (1) |

Note (1) Stresses beyond those listed in above “ELECTRICAL ABSOLUTE RATINGS” may cause permanent damage to the device. Normal operation should be restricted to the conditions described in “ELECTRICAL CHARACTERISTICS”.

7. Reliability Test Item of TDM

| Test Item | Test Condition | Note |
|----------------------------------|--|---------|
| Temperature Humidity Bias (THB) | Ta= 50℃ , 80%RH, 240hours | (1) (2) |
| High Temperature Operation (HTO) | Ta= 50℃ , 240hours | |
| Low Temperature Operation (LTO) | Ta= -10℃ , 240hours | |
| High Temperature Storage (HTS) | Ta= 60℃ , 240hours | |
| Low Temperature Storage (LTS) | Ta= -20℃ , 240hours | |
| Thermal Shock Test (TST) | -20℃/30min , 60℃ / 30min , 100 cycles | |
| ESD Test(Operation) | 150pF, 330Ω, 1sec/cycle Condition 1 : Contact Discharge, ±8KV | (1) |
| | 150pF, 330Ω, 1sec/cycle Condition 2 : Air Discharge, ±12KV | |
| Shock (Non-Operating) | (non-operation) 220G, 2ms, half sine wave, 1 time for each direction of ±X, ±Y, ±Z | (1) (3) |
| Vibration (Non-Operating) | (non-operation) 1.5G/10-500 Hz, Sine wave, 30 min/cycle, 1cycle for each X, Y, Z | (1) (3) |

Note (1) Criteria : Normal display image with no obvious non-uniformity and no line defect.

Note (2) Evaluation should be tested after storage at room temperature for more than two hours.

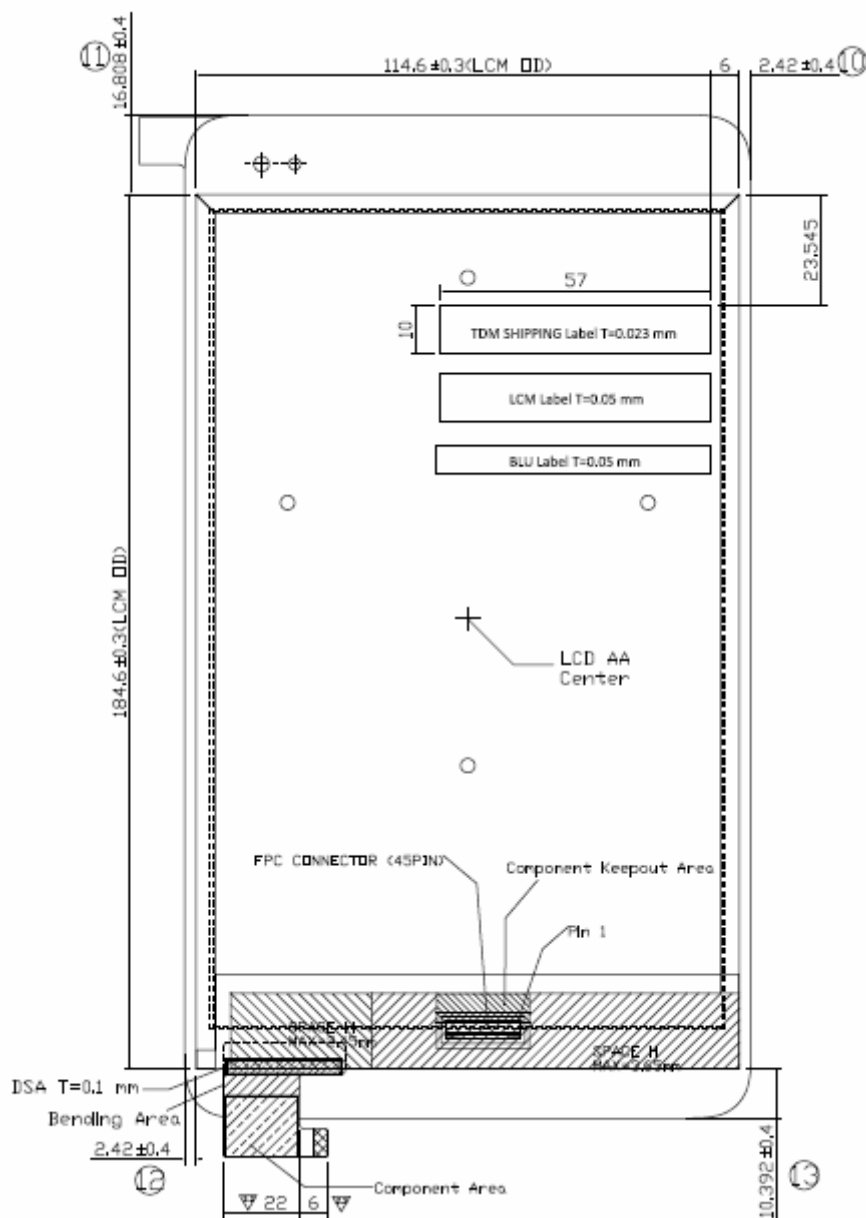
Note (3) At testing Vibration and Shock, the fixture in holding the module has to be hard and rigid enough so that the module would not be twisted or bent by the fixture.

8. Shipping and Package of TDM

8.1 Label Position

(a) Label : Means TDM Label

(b) Module Label : Means LCM Label




8.2 Label Definition of TDM

(a) Carton Label Format

PO.NO. _____

Part ID. **GP080LDEF020S**

Model Name **P080LDE-DF1**

Carton ID.  Quantities **30**

ATXYMDLNNN

GP

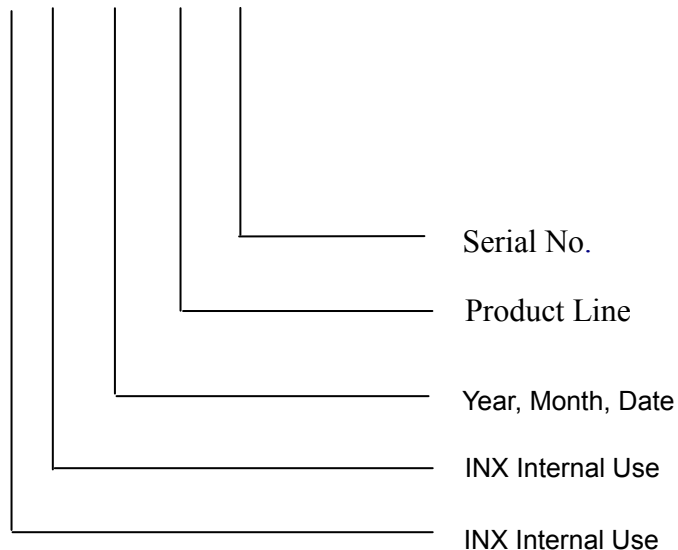
RoHS

填入成品料號

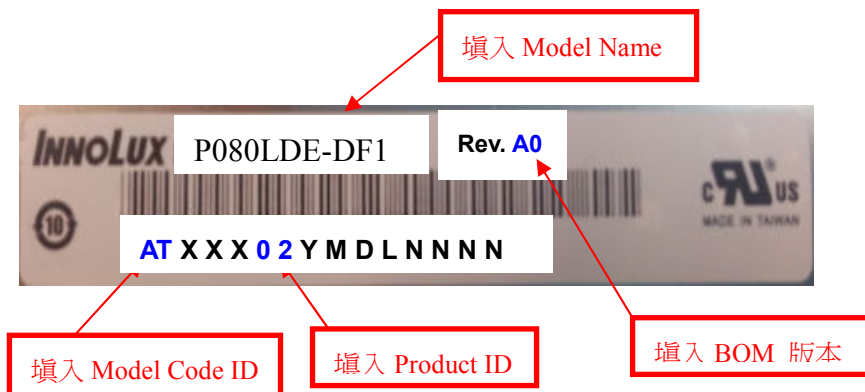
填入 Model Name

填入每個 carton 的 panel 數量

(a) Carton ID: ATXYMDLNNN



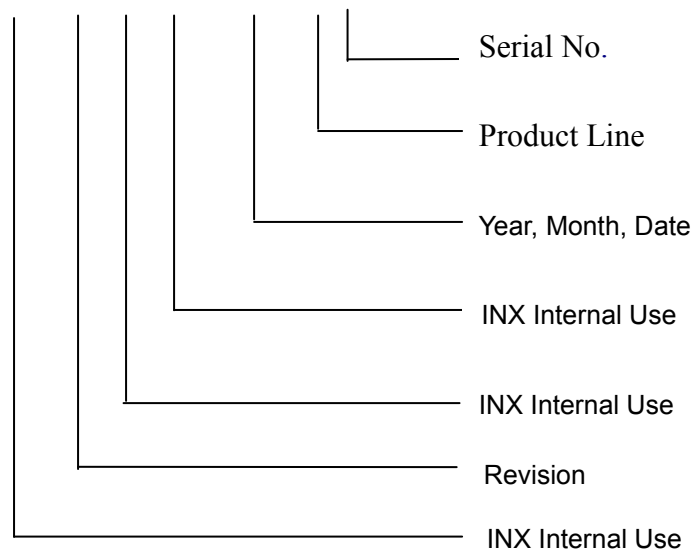
(b)SN Label Definition



(a) Model Name: **P080LDE-DF1**

(b) Revision: Rev. **A0**, for example: C1, C2 ...etc.

(c) Serial ID: X X X X X X X Y M D L N N N N



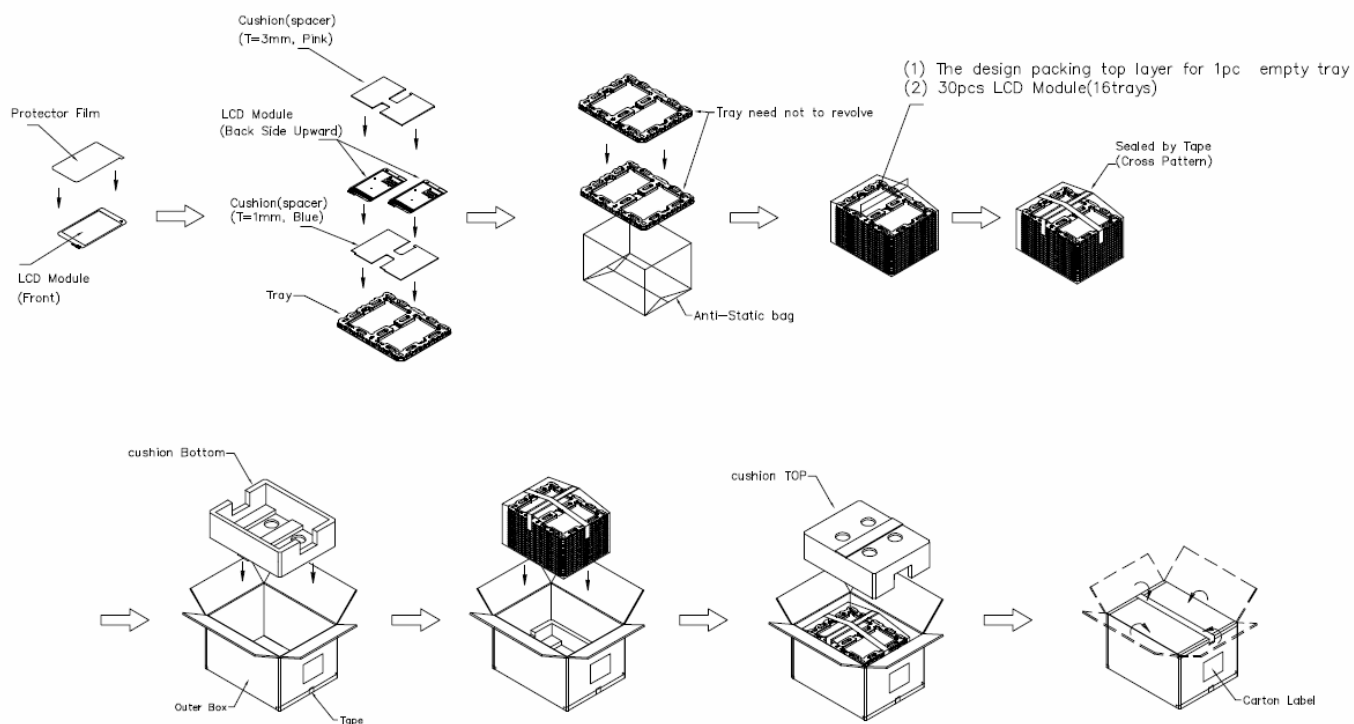
(d) Production Location: MADE IN XXXX. XXXX stands for production location.

(e) UL logo: “AAAA” especially stands for panel manufactured by INX China satisfying UL requirement.

“LEOO” and “COCKN” is the INX’s UL factory code for Ningbo factory..

8.3 Package of TDM

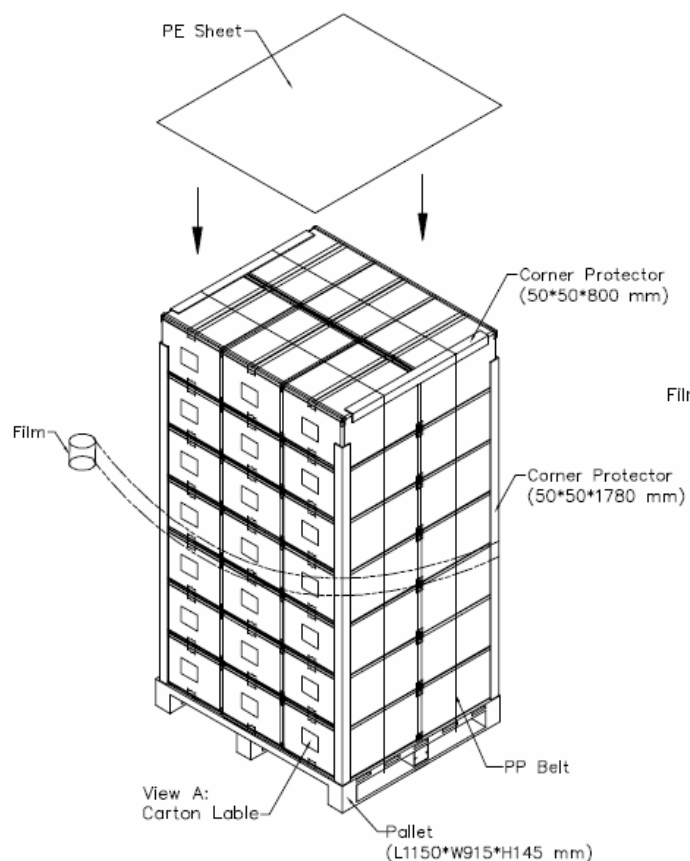
(a) Packing



- (1) Box Dimensions : 435(L)*350(W)*275(H)
- (2) 30 Modules/Carton

Figure. 7-1 Packing method

Sea & Land Transportation



Air Transportation

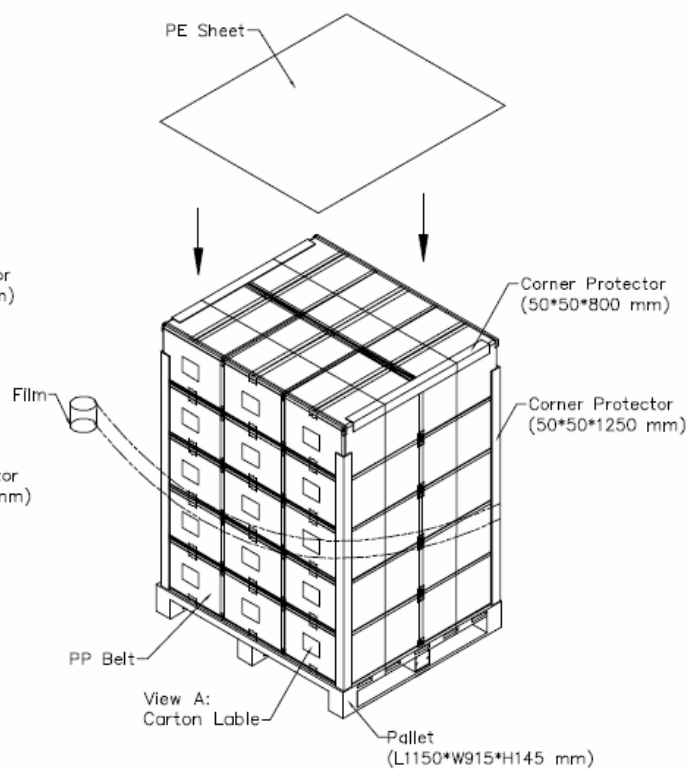


Figure. 7-2 Packing method

(b) Un-Packing

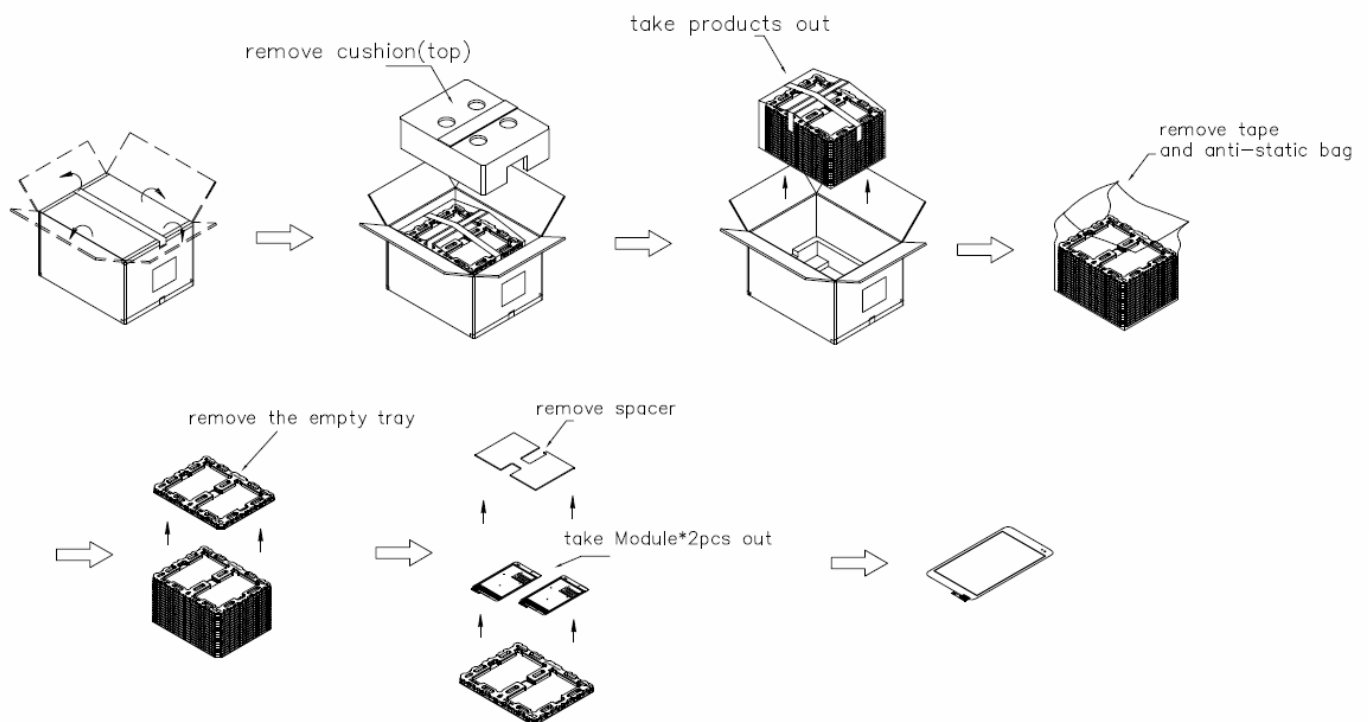


Figure. 7-3 Un-Packing method

9. Precautions

9.1 Handling Precautions

- (1) The module should be assembled into the system firmly by using every mounting hole. Be careful not to twist or bend the module.
- (2) While assembling or installing modules, it can only be in the clean area. The dust and oil may cause electrical short or damage the polarizer.
- (3) Use fingerstalls or soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (4) Do not press or scratch the surface harder than a HB pencil lead on the panel because the polarizer is very soft and easily scratched.
- (5) If the surface of the polarizer is dirty, please clean it by some absorbent cotton or soft cloth. Do not use Ketone type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanently damage the polarizer due to chemical reaction.
- (6) Wipe off water droplets or oil immediately. Staining and discoloration may occur if they left on panel for a long time.
- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contacting with hands, legs or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static electricity, it may cause damage to the C-MOS Gate Array IC.
- (9) Do not disassemble the module.
- (10) Do not pull or fold the LED wire.
- (11) Pins of I/F connector should not be touched directly with bare hands.

9.2 Storage Precautions

- (1) High temperature or humidity may reduce the performance of module. Please store LCD module within the specified storage conditions.
- (2) It is dangerous that moisture come into or contacted the LCD module, because the moisture may damage LCD module when it is operating.
- (3) It may reduce the display quality if the ambient temperature is lower than 10 °C. For example, the response time will become slowly, and the starting voltage of LED will be higher than the room temperature.

9.3 Operation Precautions

- (1) Do not pull the I/F connector in or out while the module is operating.

- (2) Always follow the correct power on/off sequence when LCD module is connecting and operating. This can prevent the CMOS LSI chips from damage during latch-up.
- (3) The startup voltage of Backlight is approximately 1000 Volts. It may cause electrical shock while assembling with converter. Do not disassemble the module or insert anything into the Backlight unit.
- (4) ight unit.